D

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C

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TPS71712
SHEET 6

TPS79618
TPS71733
SHEET 12

A

TPS76750
SHEETS 6, 25, 27

TPS73533
TPS71750
SHEET 20

NOTE: DNI = DO NOT INSTALL COMPONENT.

TEXAS INSTRUMENTS

Engineer: C. PEARSON
PCB Designer:JV SMITH

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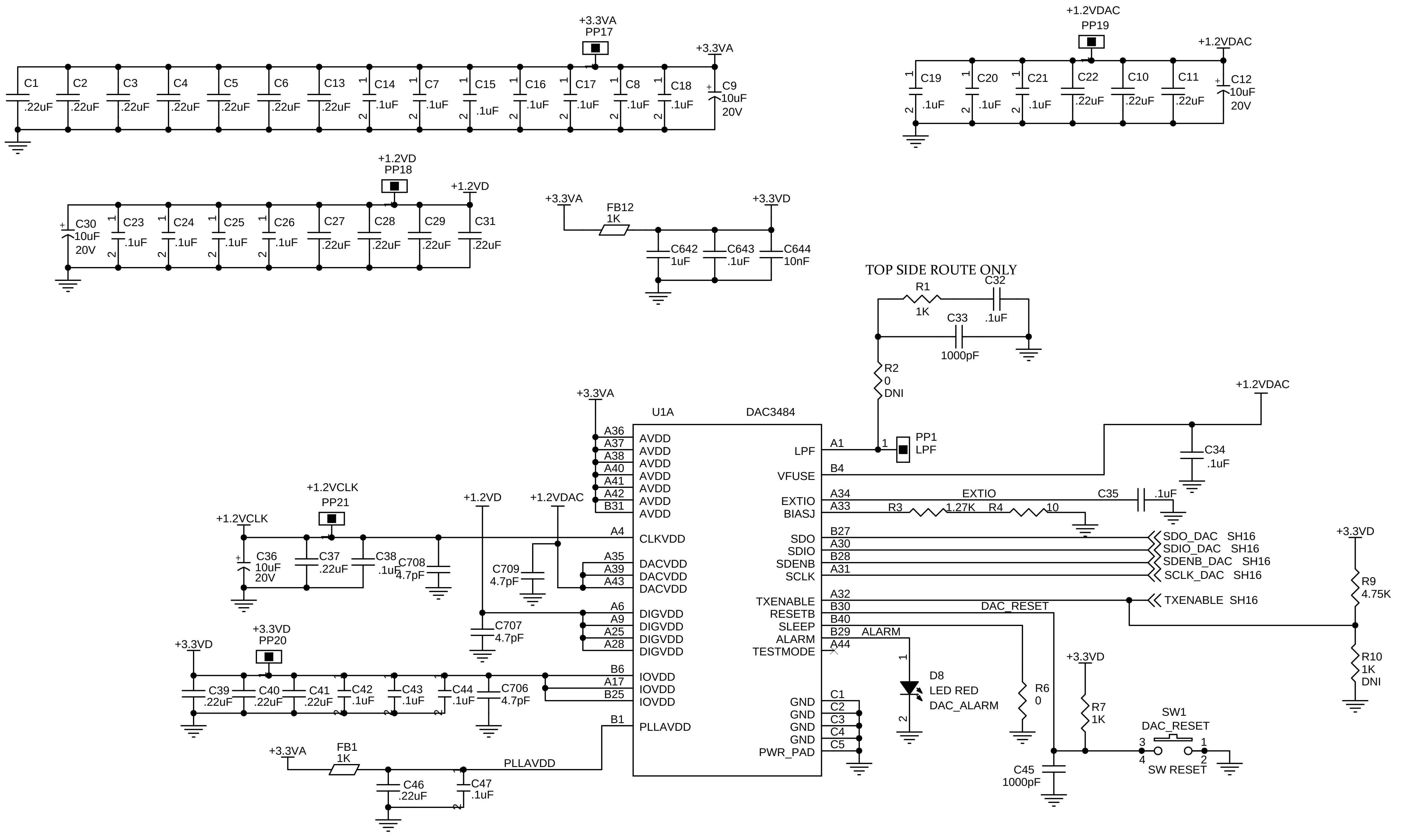

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Title: *TSW3725*

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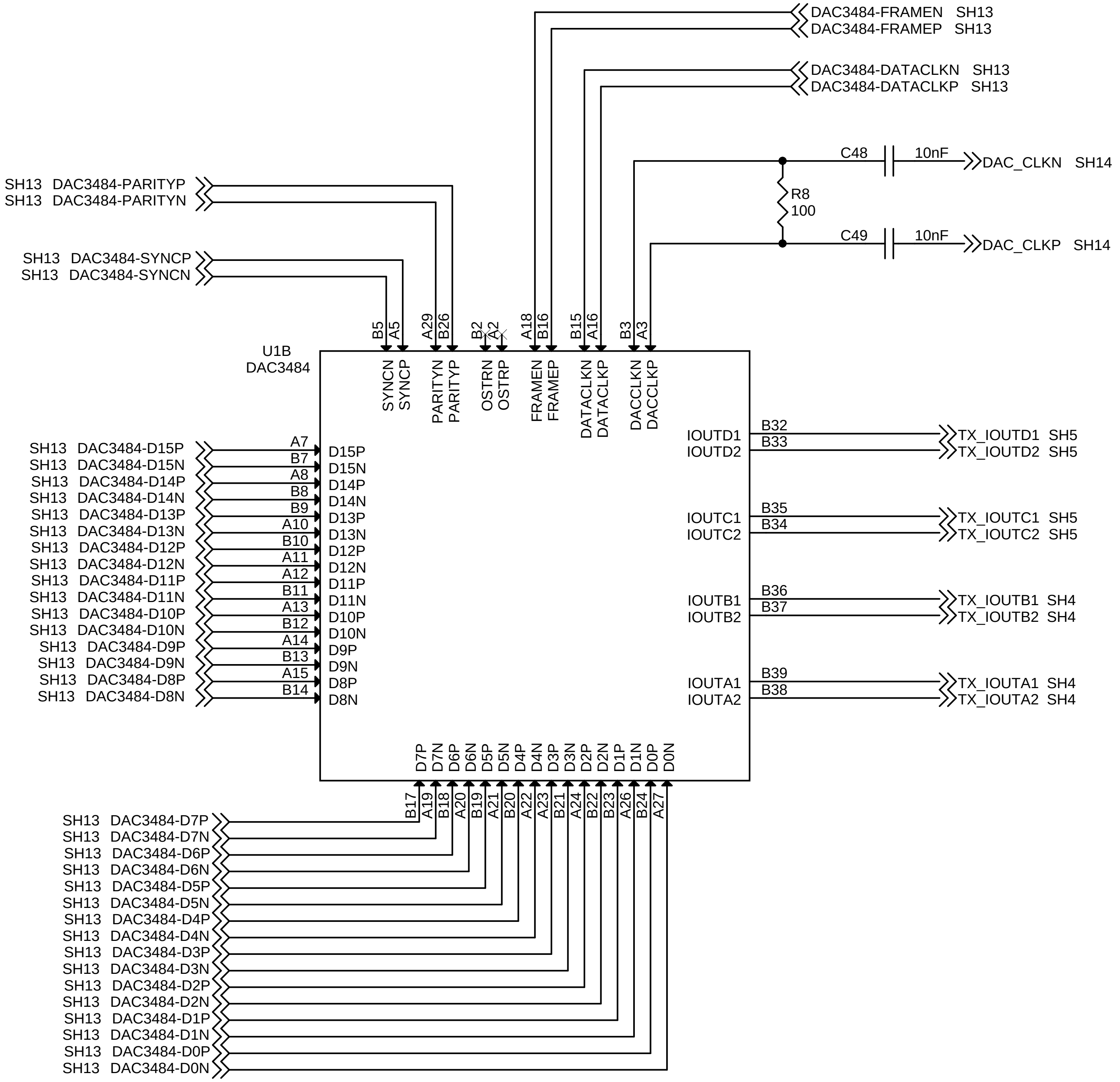
TRANSMIT DAC



TEXAS INSTRUMENTS

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TSW3725

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MULTI-FREQ DAC
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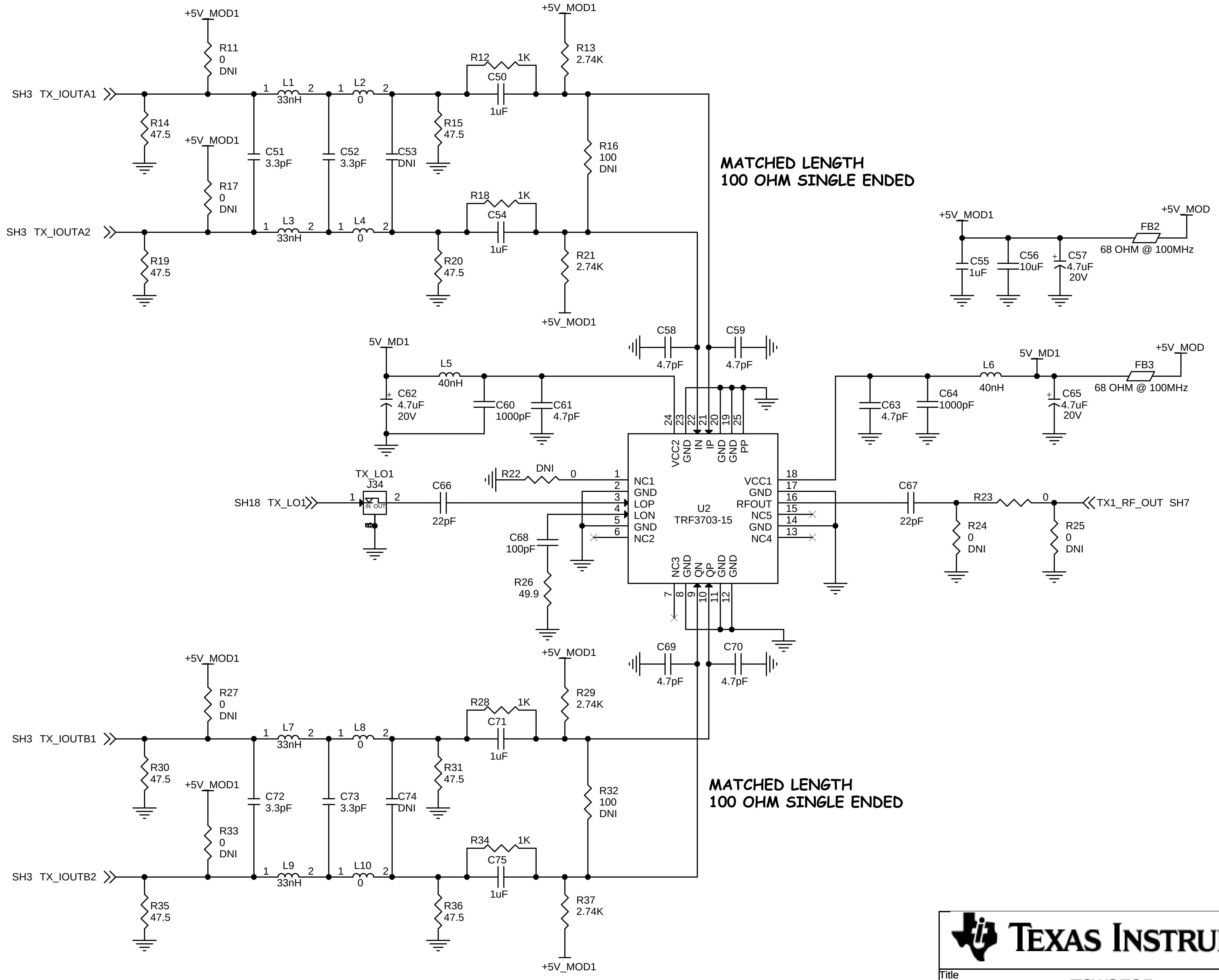

TEXAS INSTRUMENTS

Title
TSW3725

Size B
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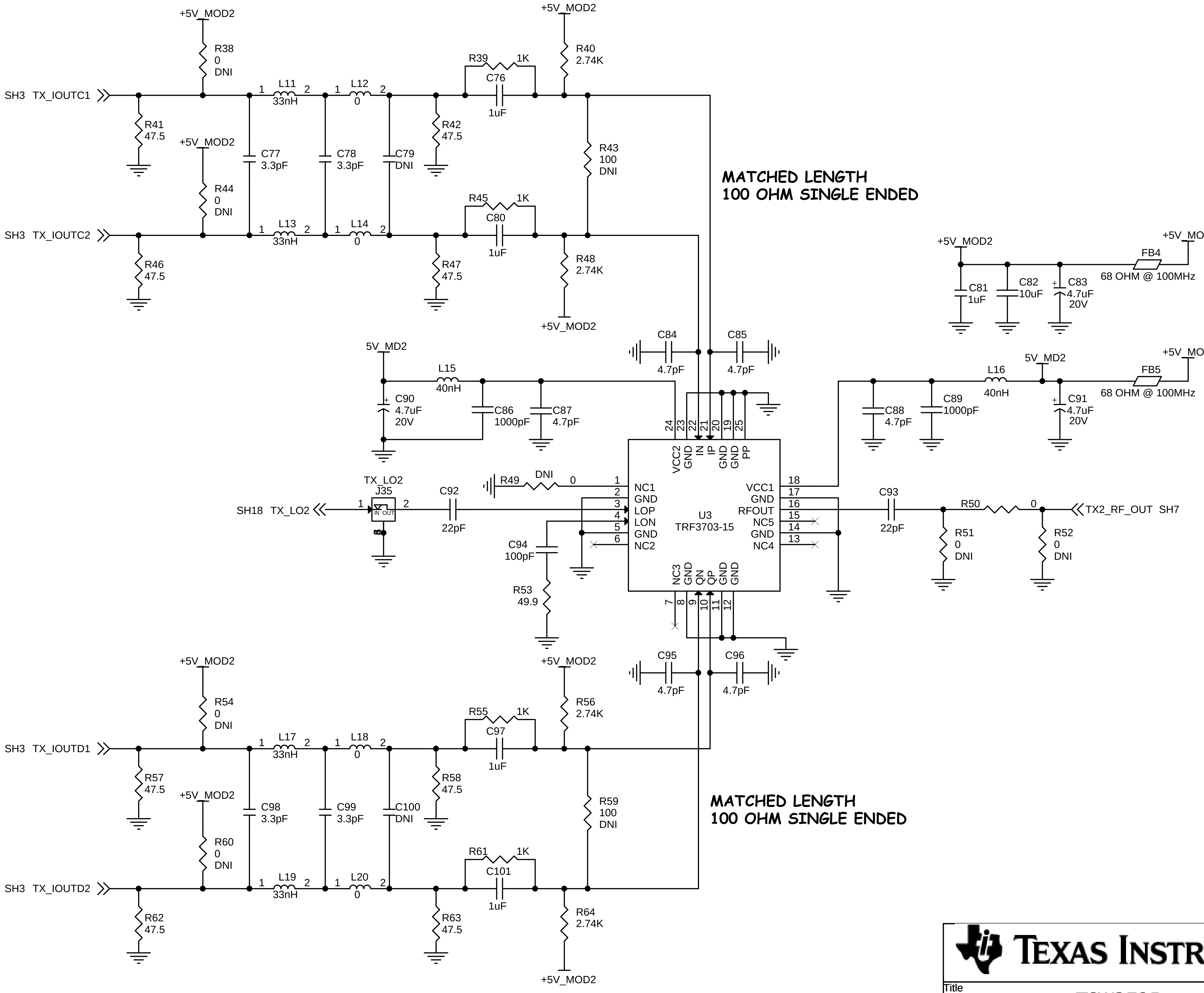

TEXAS INSTRUMENTS

Title
TSW3725

Size
B

Document Number
MULTI-FREQ MODULATOR

Rev
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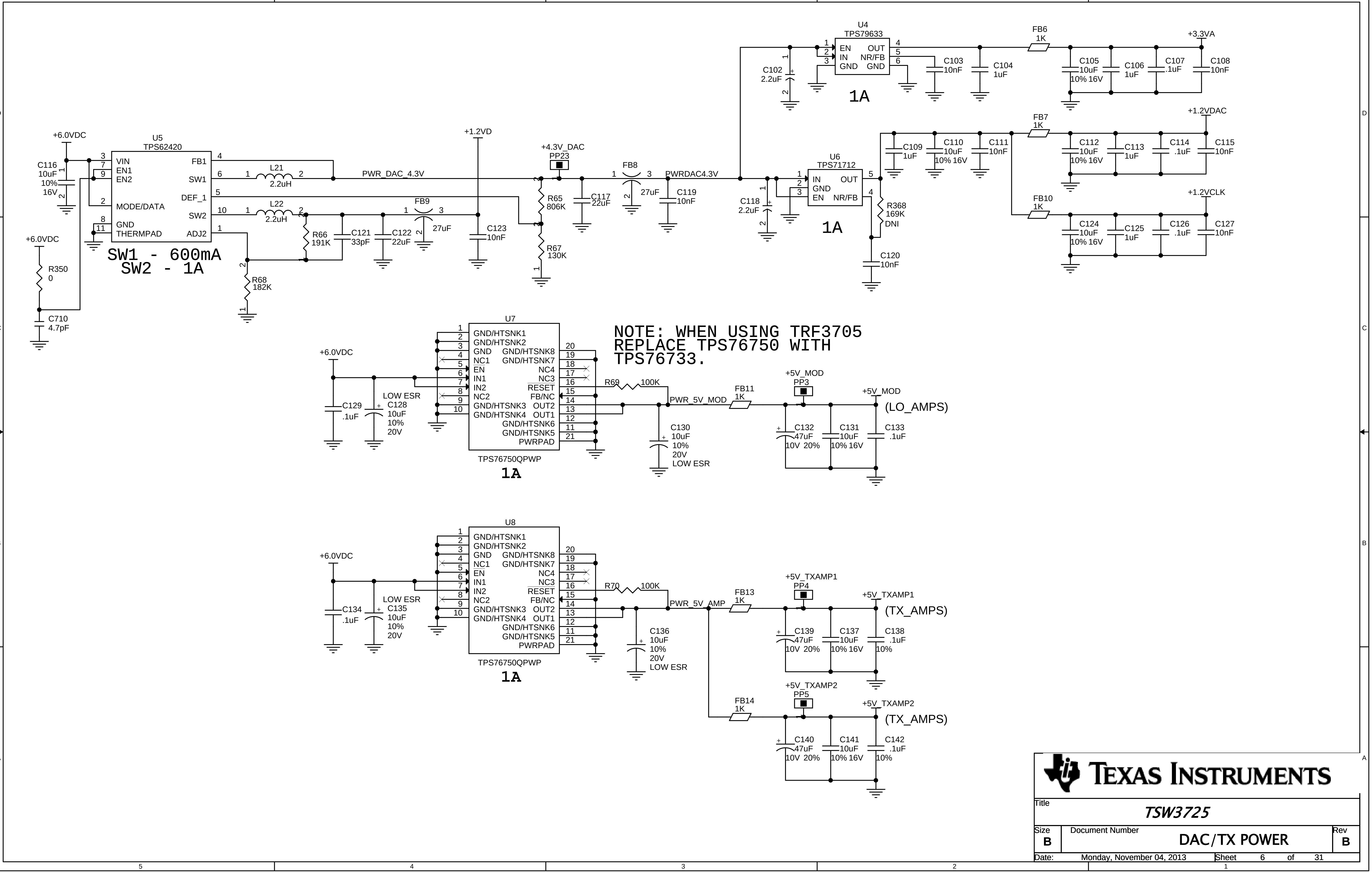

NOTE: WHEN USING TRF3705
REPLACE TPS76750 WITH
TPS76733.

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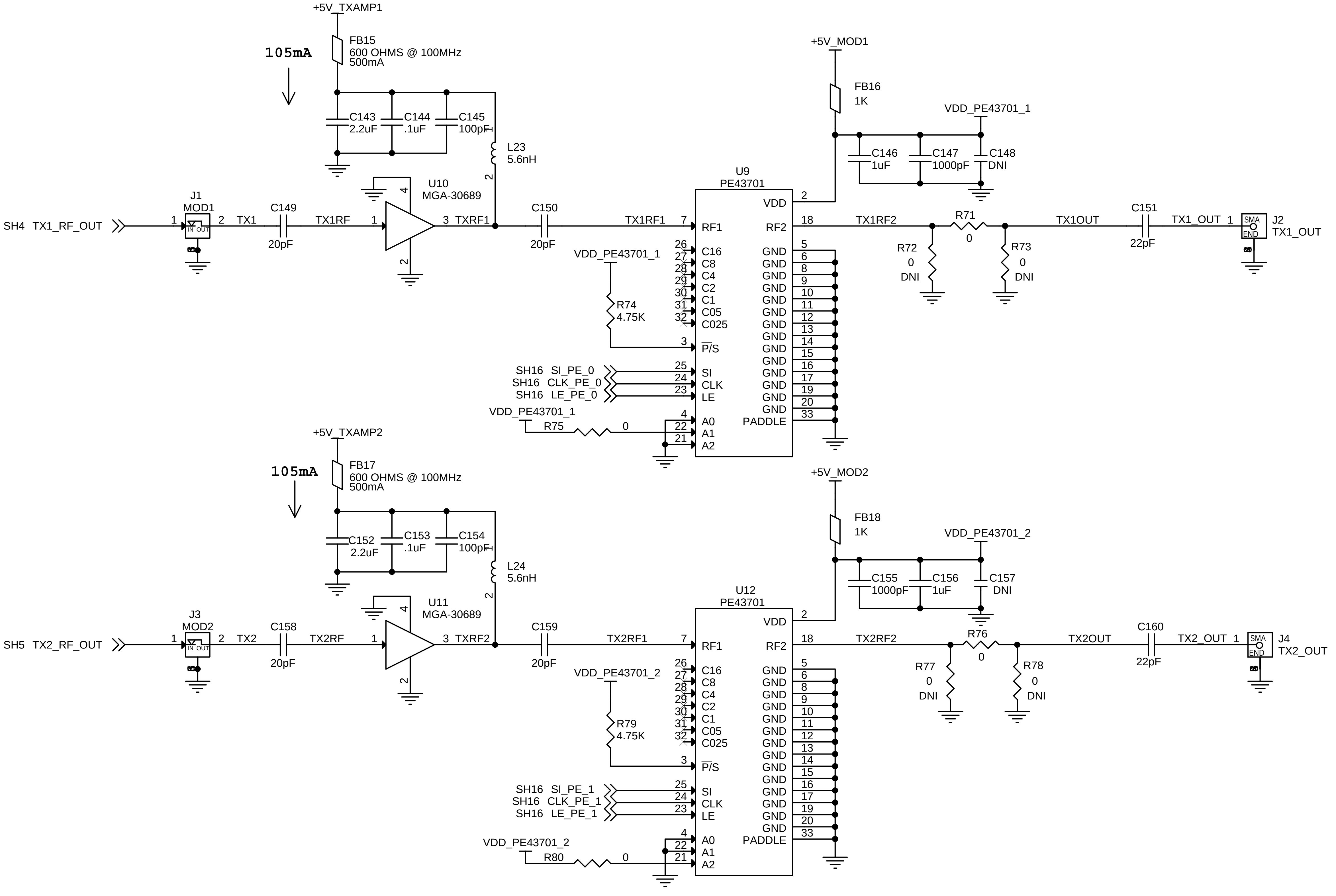
TX AMPLIFIER AND ATTENUATORS



TEXAS INSTRUMENTS

Title: *TSW3725*

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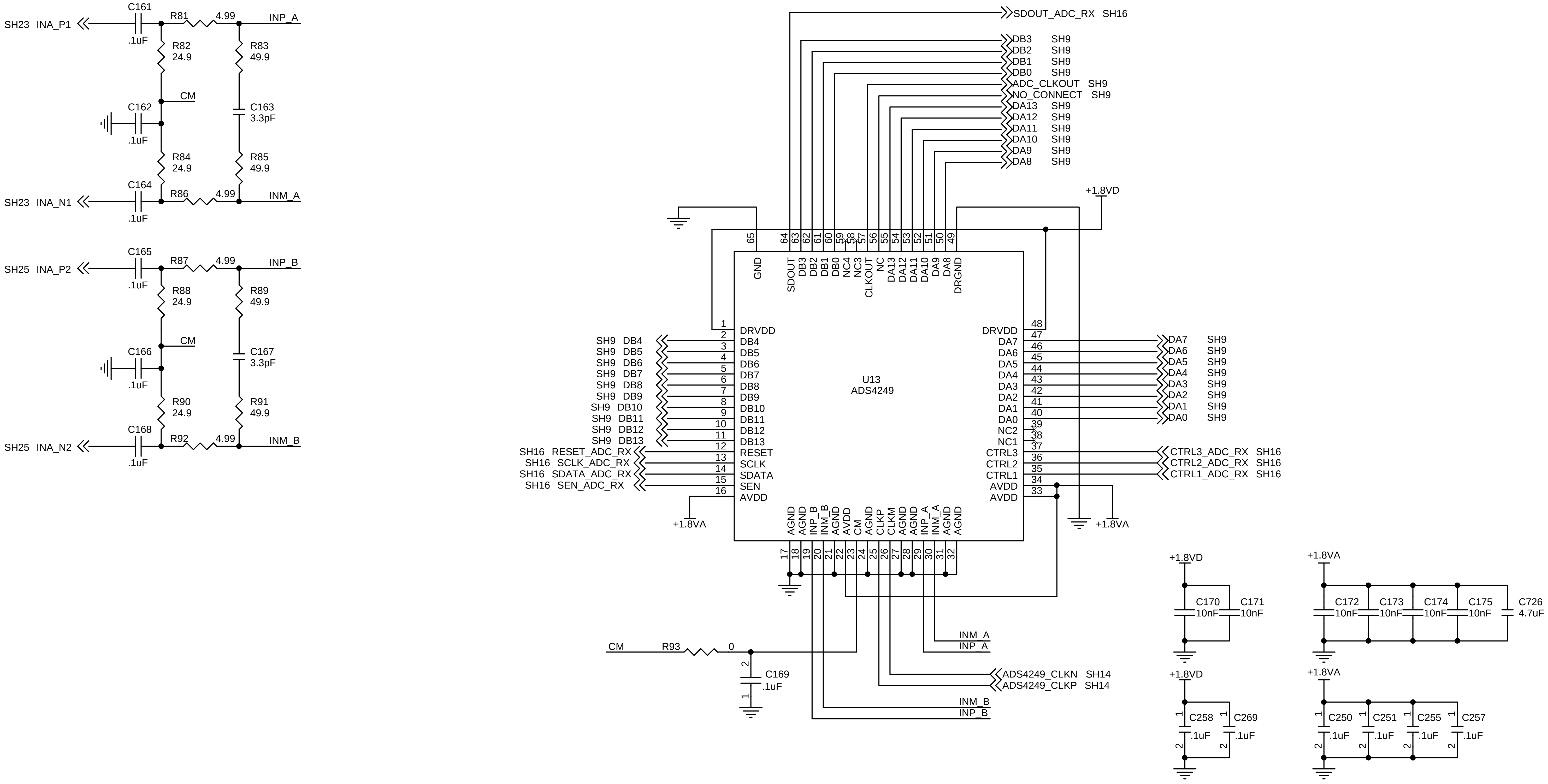

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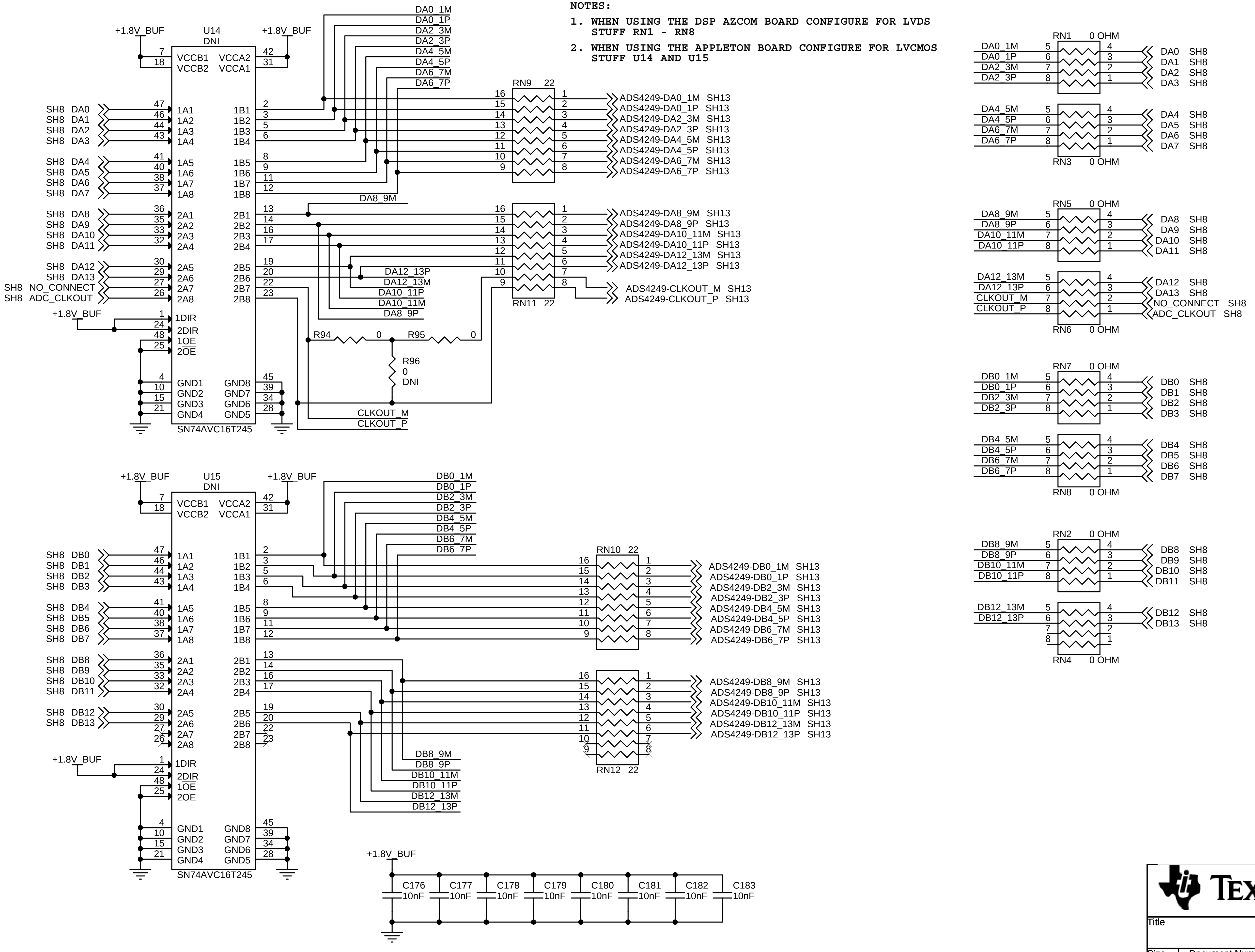
NOTES:

1. WHEN USING THE DSP AZCOM BOARD CONFIGURE FOR LVDS
   STUFF RN1 - RN8

2. WHEN USING THE APPLETON BOARD CONFIGURE FOR LVCMOS
   STUFF U14 AND U15



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Title
TSW3725

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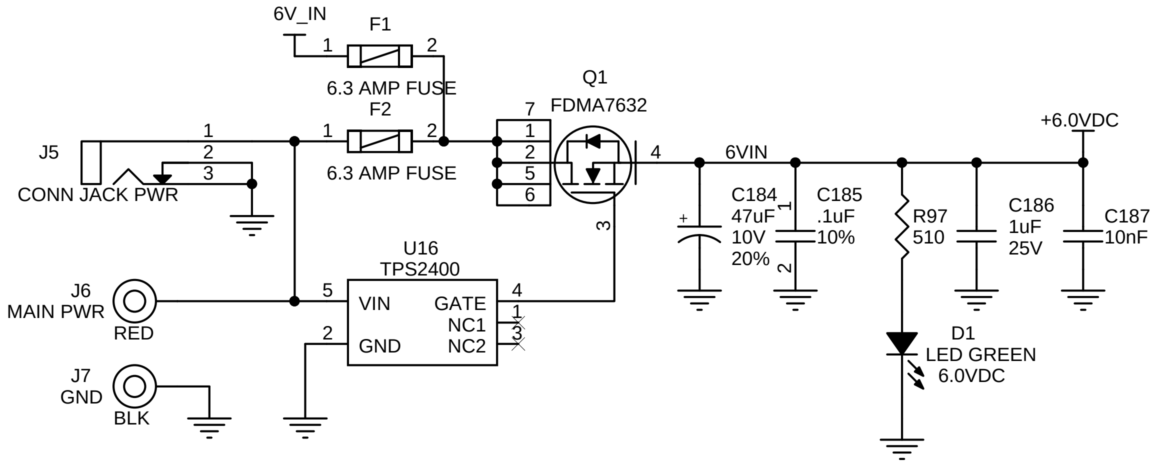
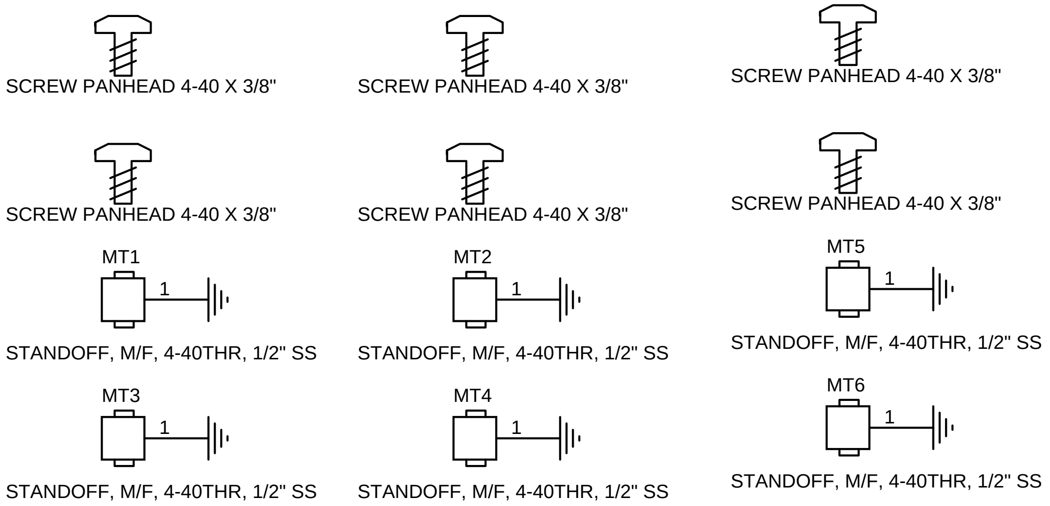


BOARD STANDOFFS AND HARDWARE

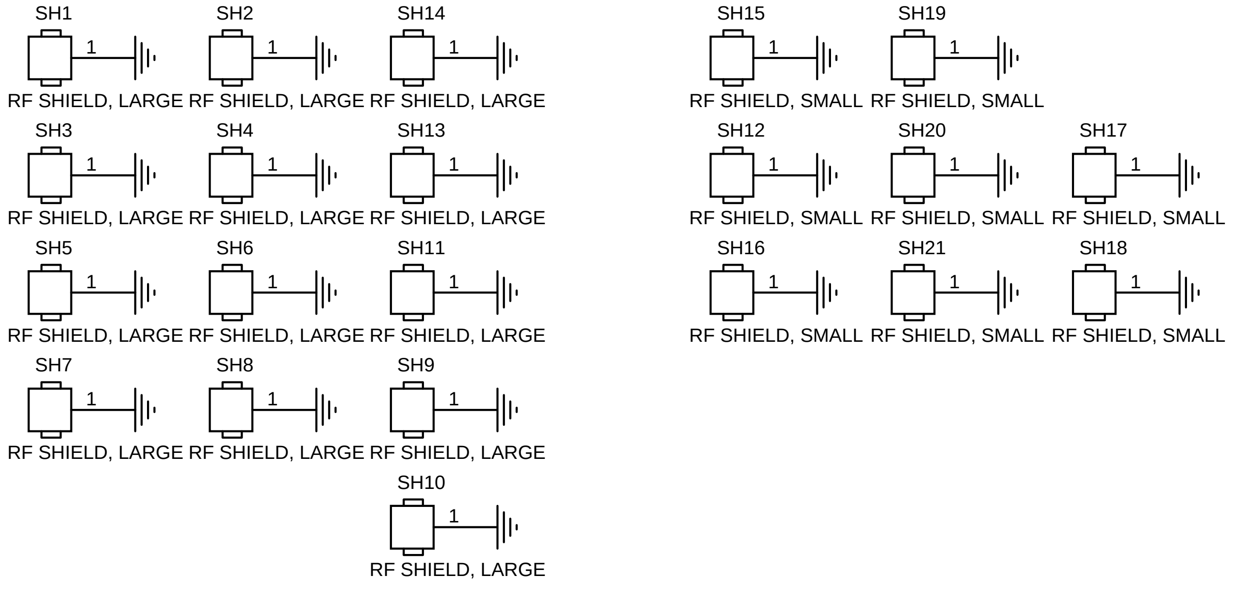


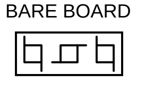
**THE BOM ADDS ANOTHER SET OF STANDOFFS
TO INCREASE THE BOARD HEIGHT.
STANDOFF, F/F, 4-40THR, 1" SS
KEYSTONE 2092

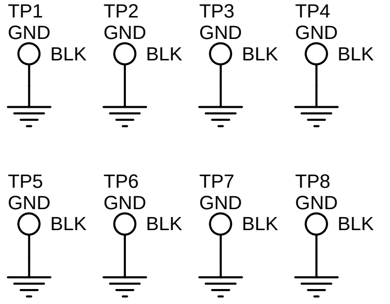
HOLES FOR THE RF SHIELDS

SL-10828

SL-10827







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Title
TSW3725

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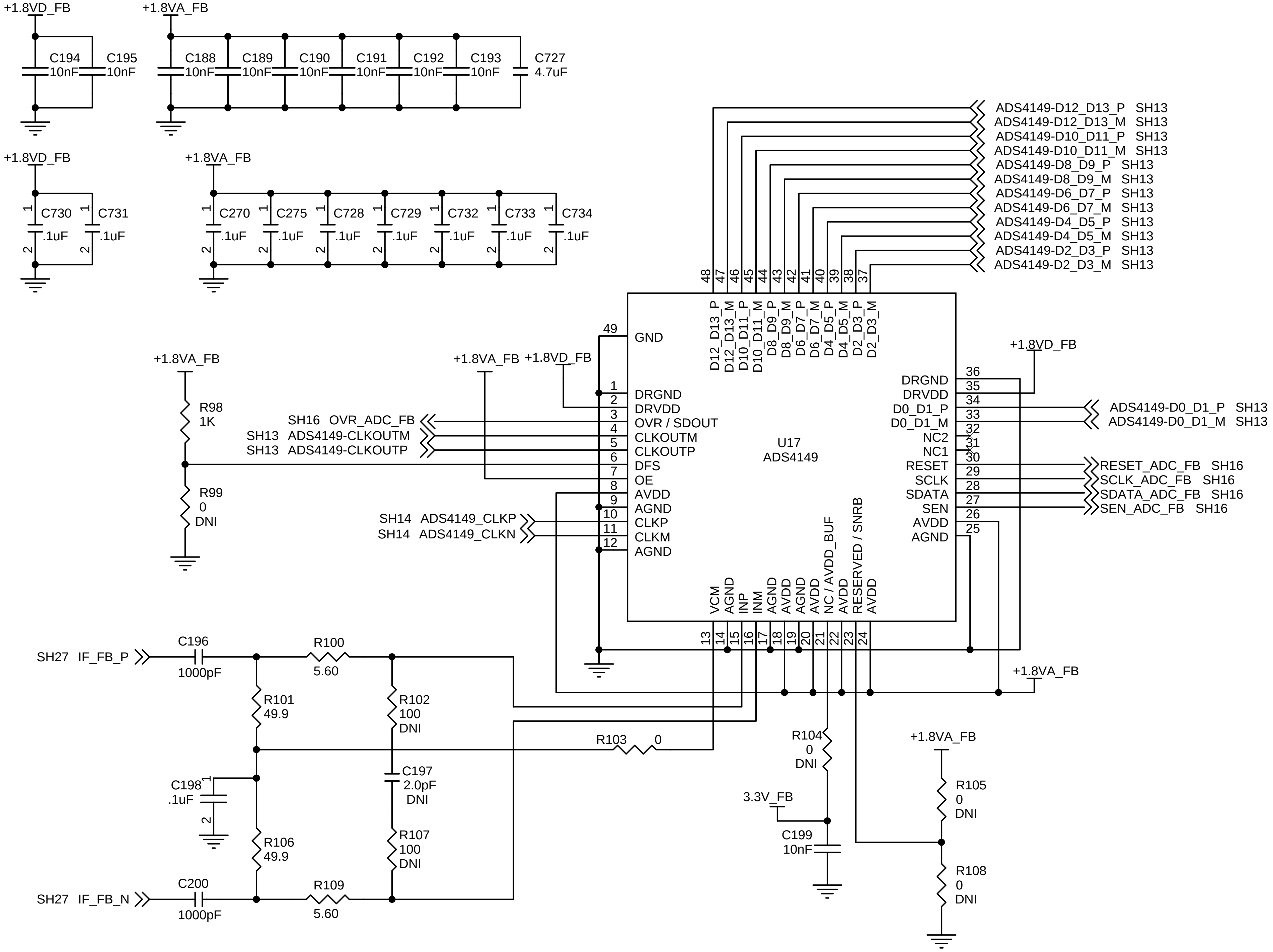
LVDS ONLY



TEXAS INSTRUMENTS

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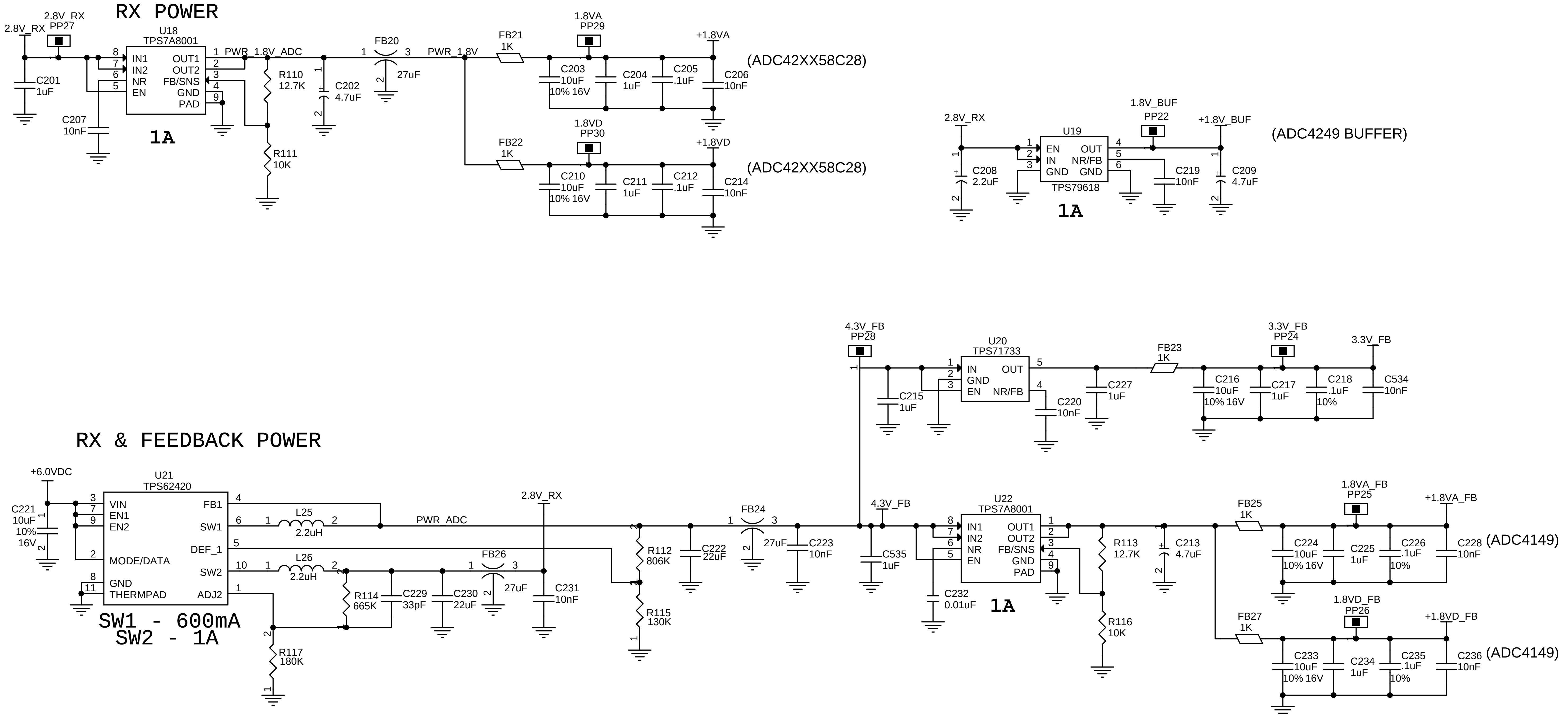

TEXAS INSTRUMENTS

Title
TSW3725

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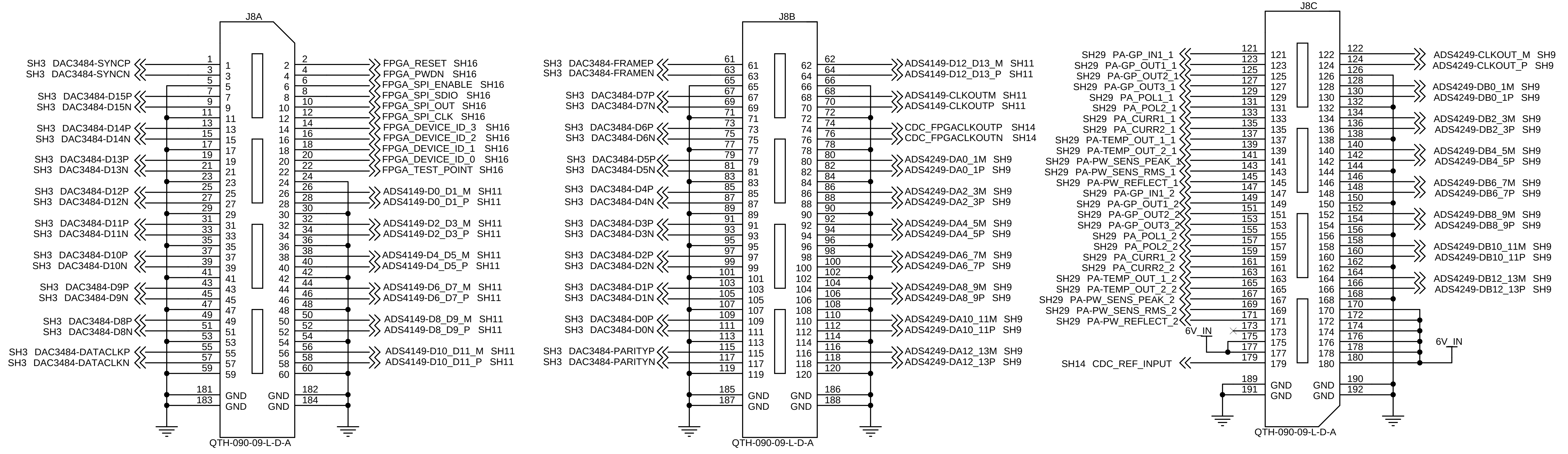

TEXAS INSTRUMENTS

Title	TSW3725	
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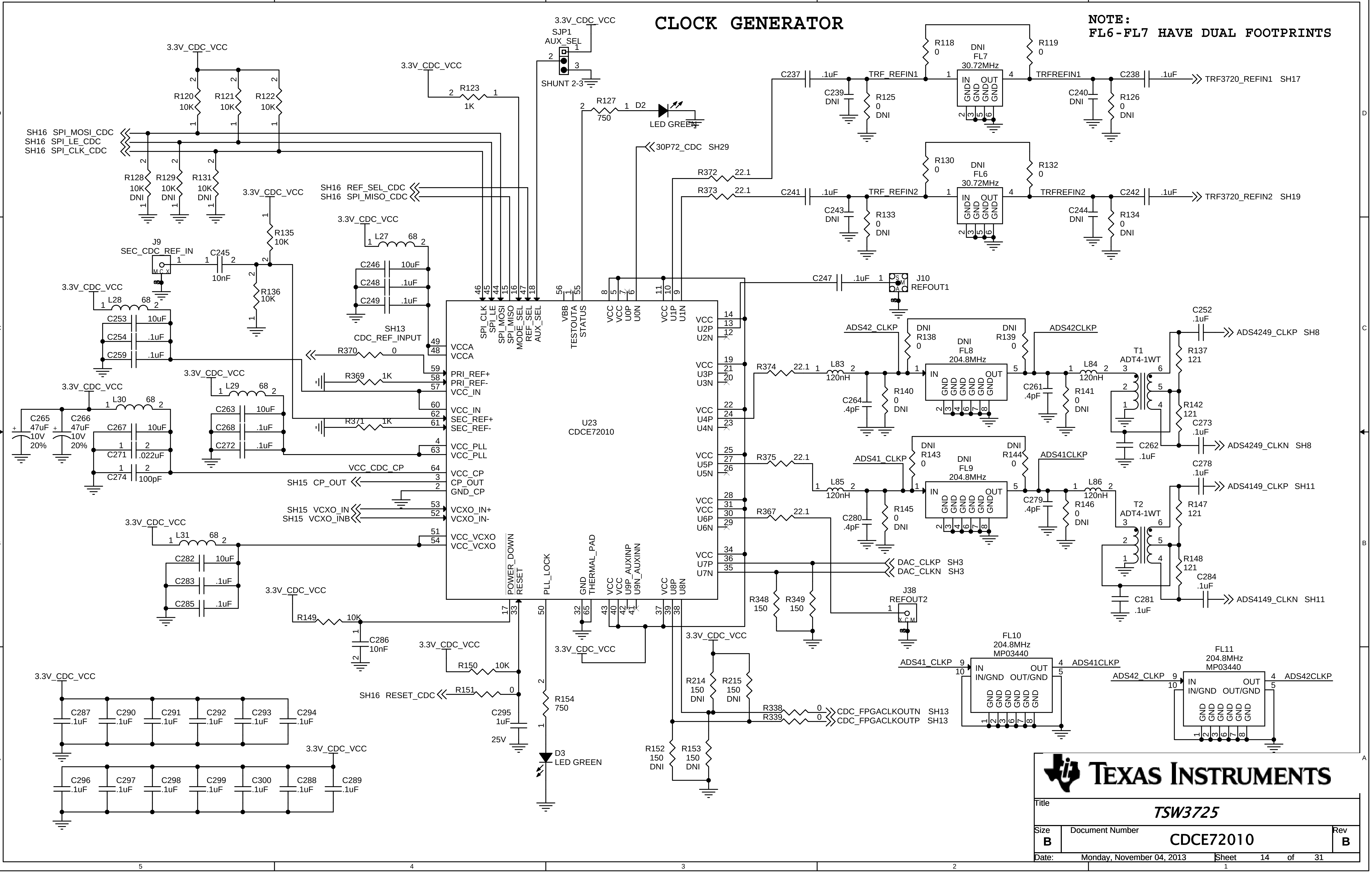
CLOCK GENERATOR

NOTE:
FL6-FL7 HAVE DUAL FOOTPRINTS



TEXAS INSTRUMENTS

Title: TSW3725

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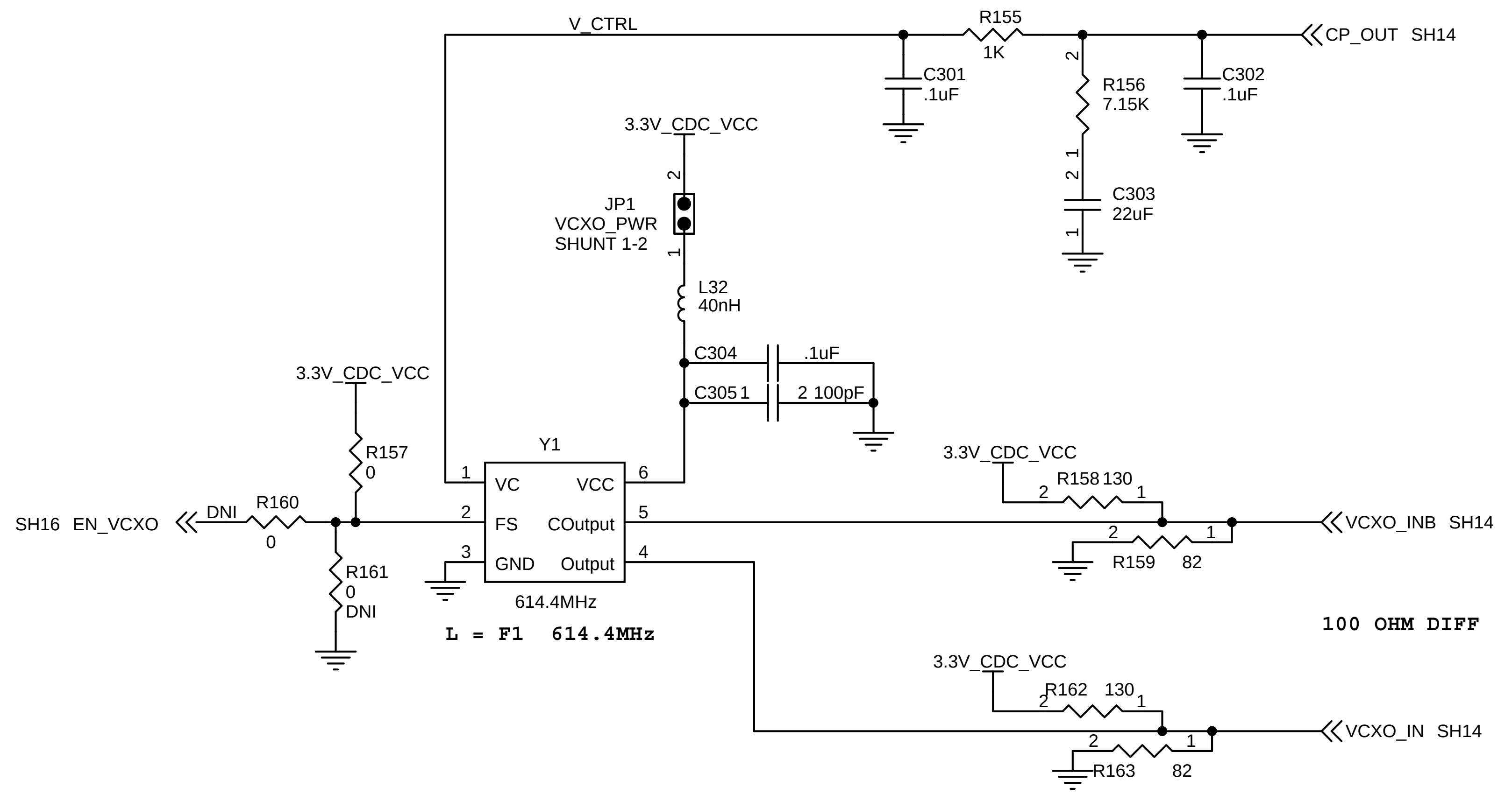
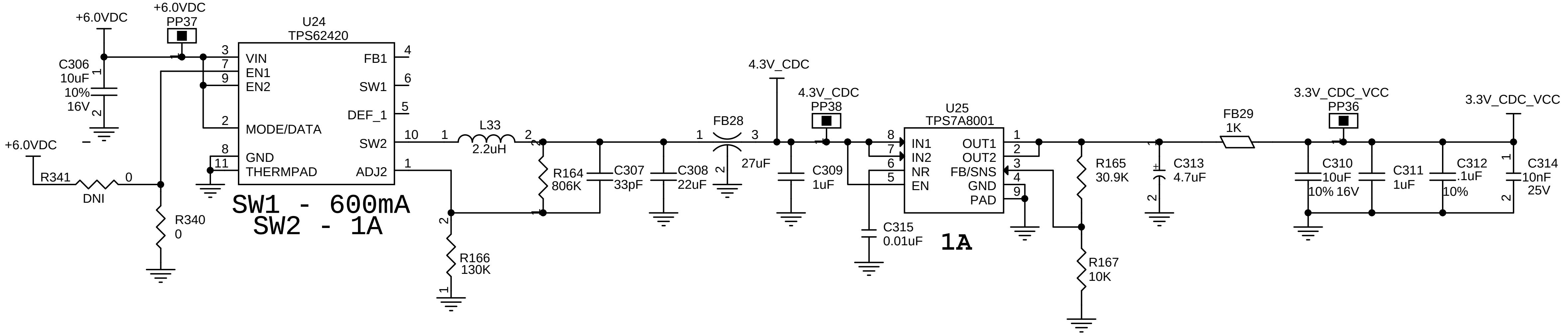
VCXO AND REFERENCE SOURCES



CDC POWER



TEXAS INSTRUMENTS

Title
TSW3725

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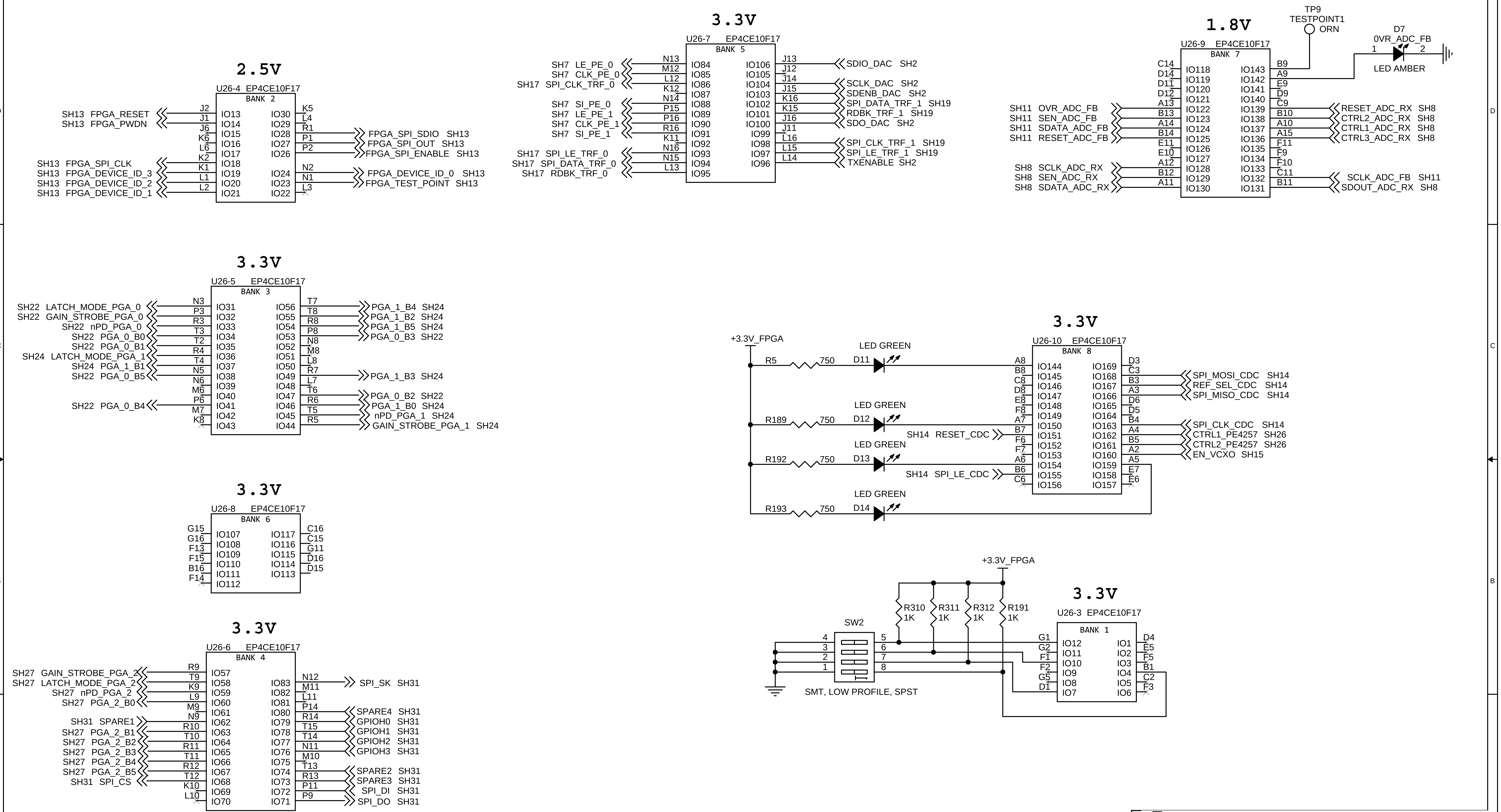

TEXAS INSTRUMENTS

Title TSW3725

Size	Document Number	Rev
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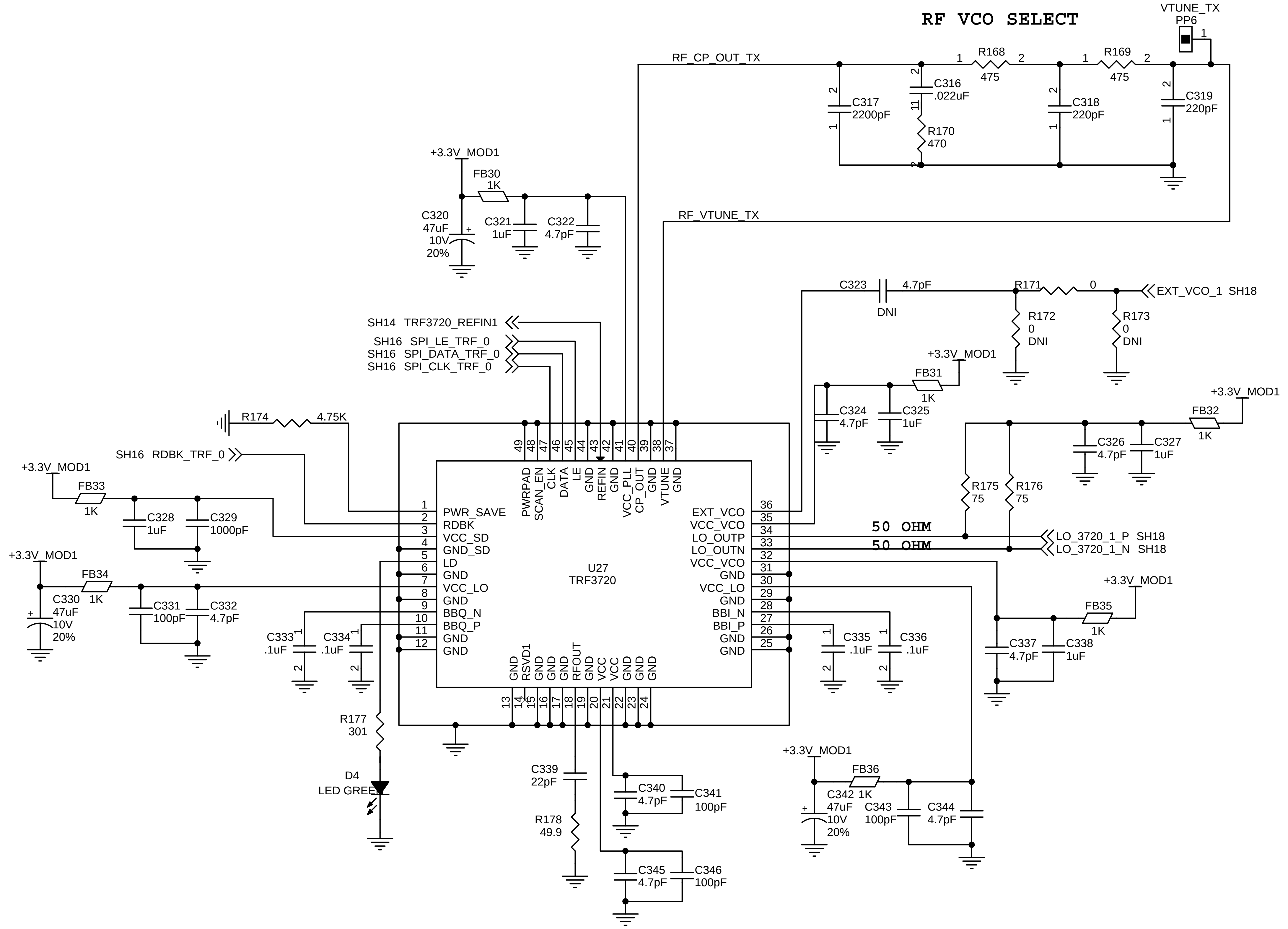

Title
TSW3725

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B	FB PATH MODULATOR	B

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LO DISTRIBUTION / BYPASS

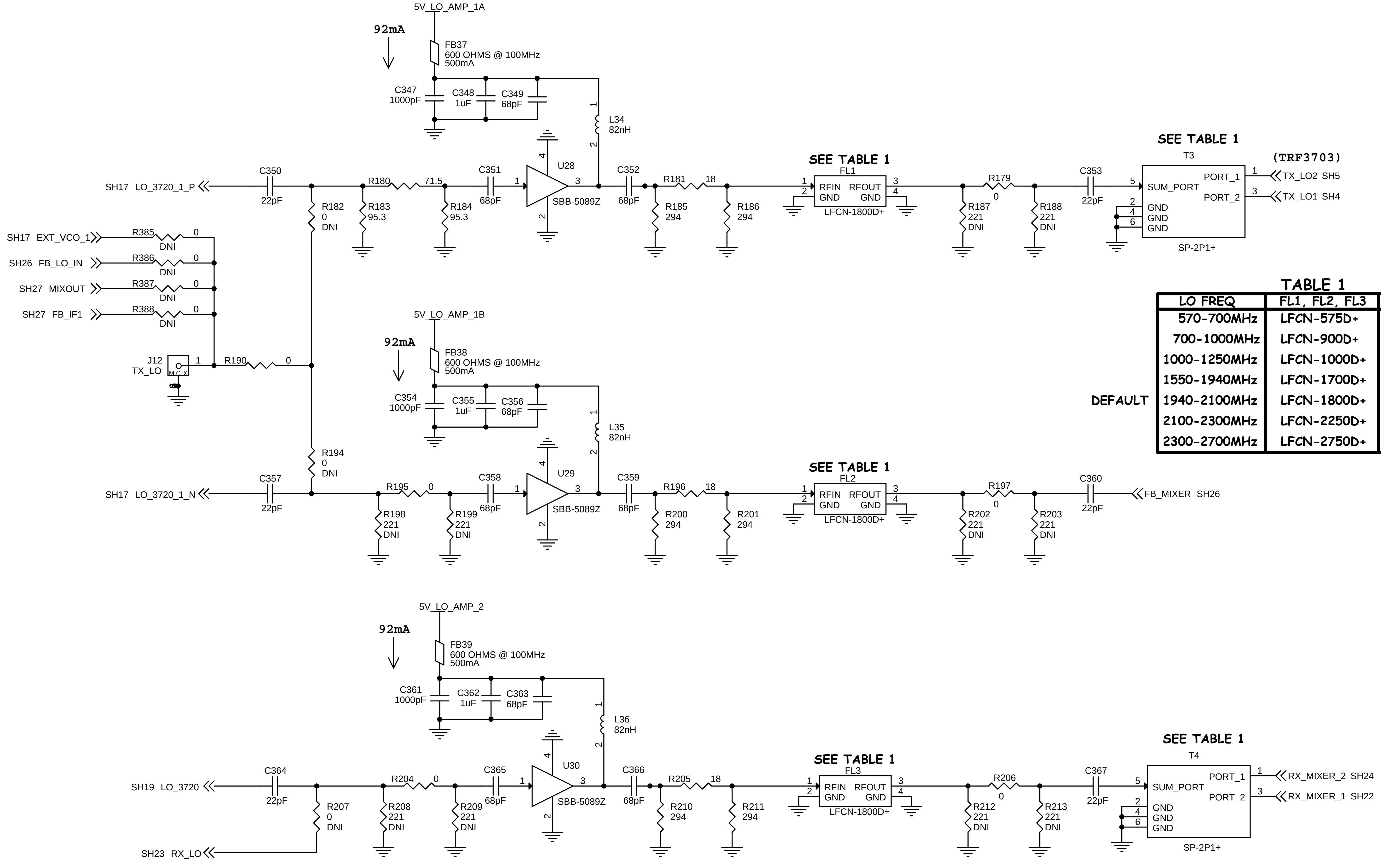

TABLE 1

	LO FREQ	FL1, FL2, FL3	T3, T4
	570-700MHz	LFCN-575D+	SP-2C1+
	700-1000MHz	LFCN-900D+	SP-2C1+
	1000-1250MHz	LFCN-1000D+	SP-2C1+
	1550-1940MHz	LFCN-1700D+	SP-2P1+
DEFAULT	1940-2100MHz	LFCN-1800D+	SP-2P1+
	2100-2300MHz	LFCN-2250D+	SP-2U1+
	2300-2700MHz	LFCN-2750D+	SP-2U1+

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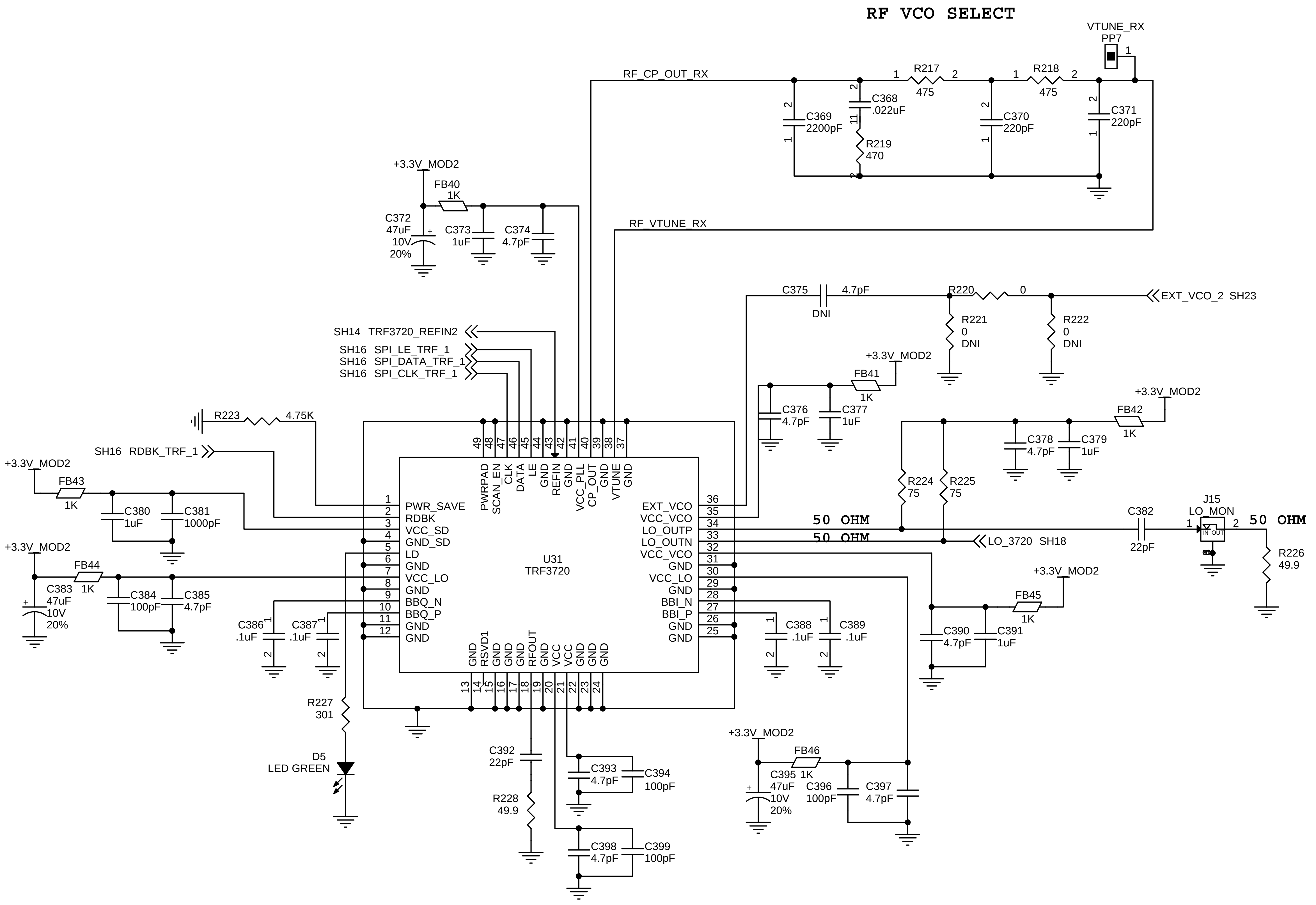
RF VCO SELECT



TEXAS INSTRUMENTS

Title: *TSW3725*

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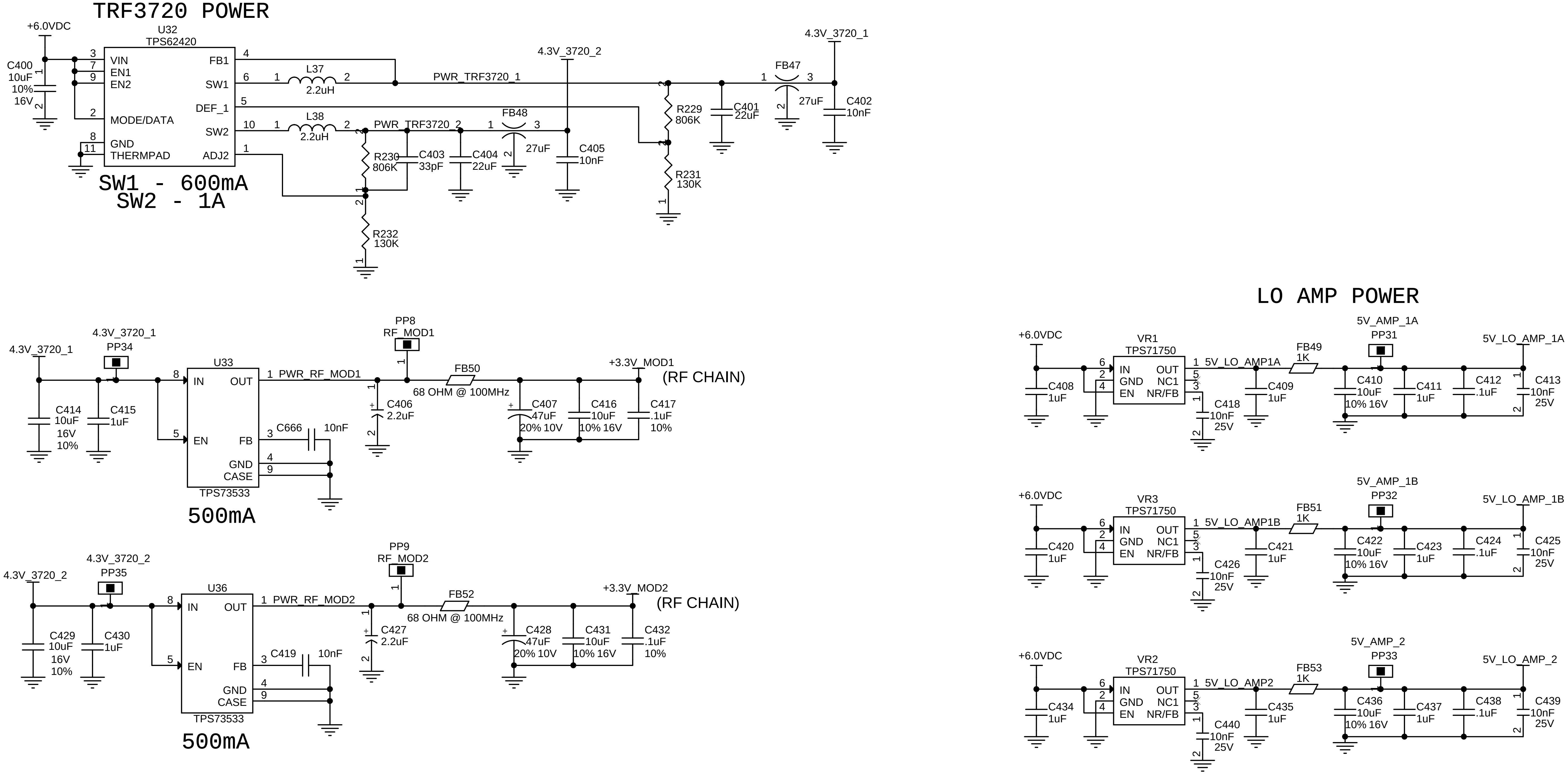

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Size B | Document Number TRF3720 & LO AMP POWER | Rev B

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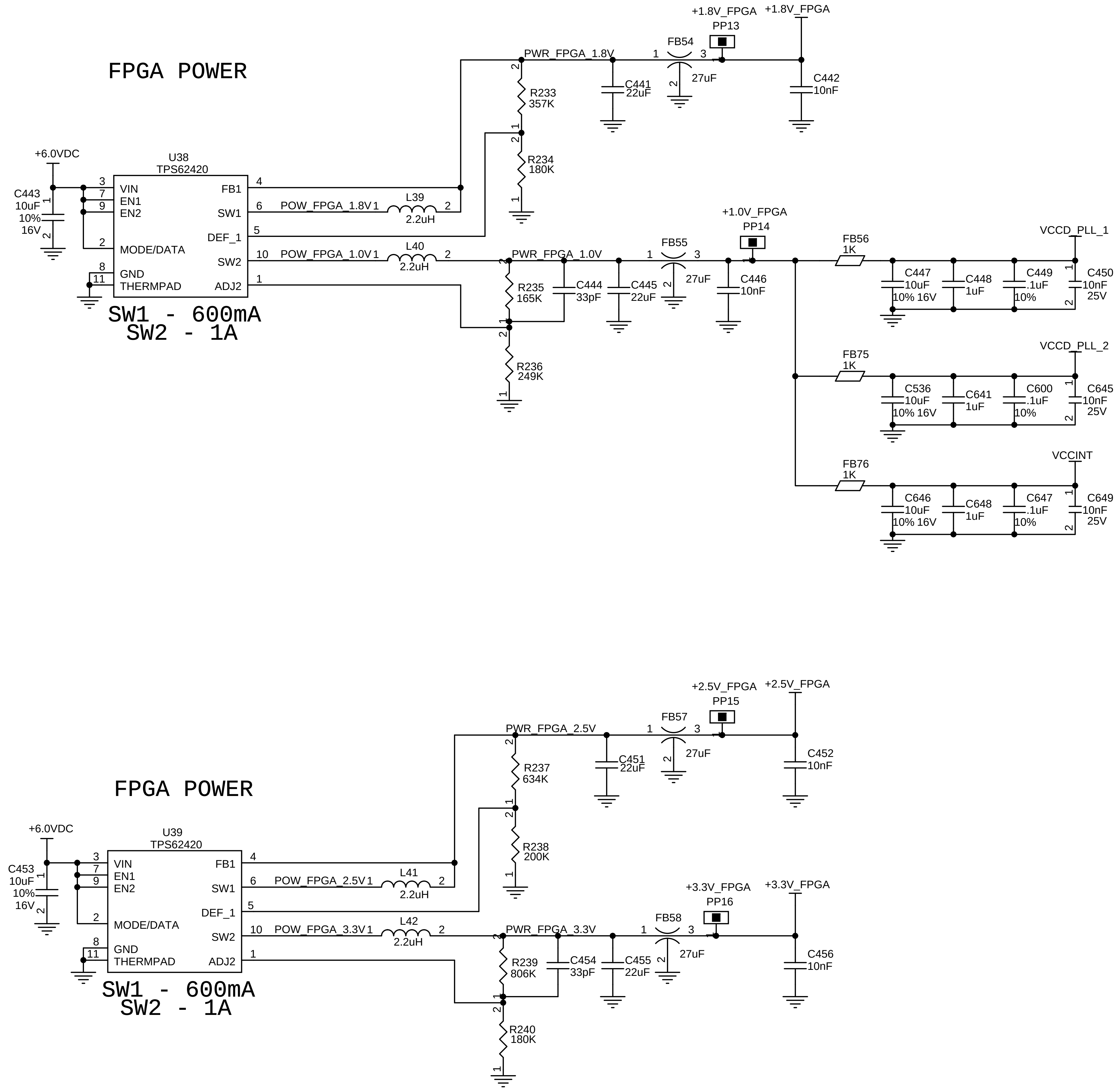

TEXAS INSTRUMENTS

Title: *TSW3725*

Size: B | Document Number: FPGA POWER | Rev: B

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RX MIXER AND AMPLIFIER
PATH 1 (RXIN1)

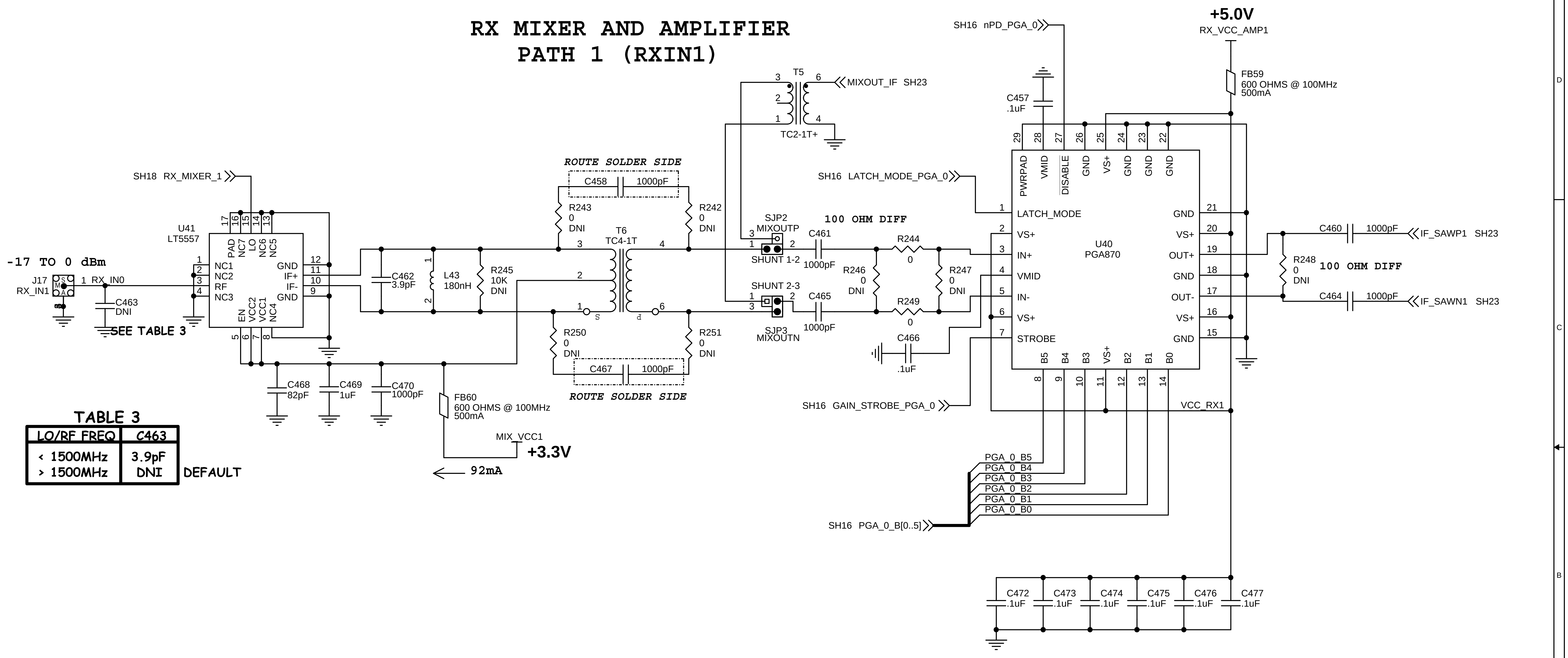

TABLE 3

LO/RF FREQ	C463
< 1500MHz	3.9pF
> 1500MHz	DNI

DEFAULT

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TSW3725

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Document Number LT5557 & PGA870 - 1
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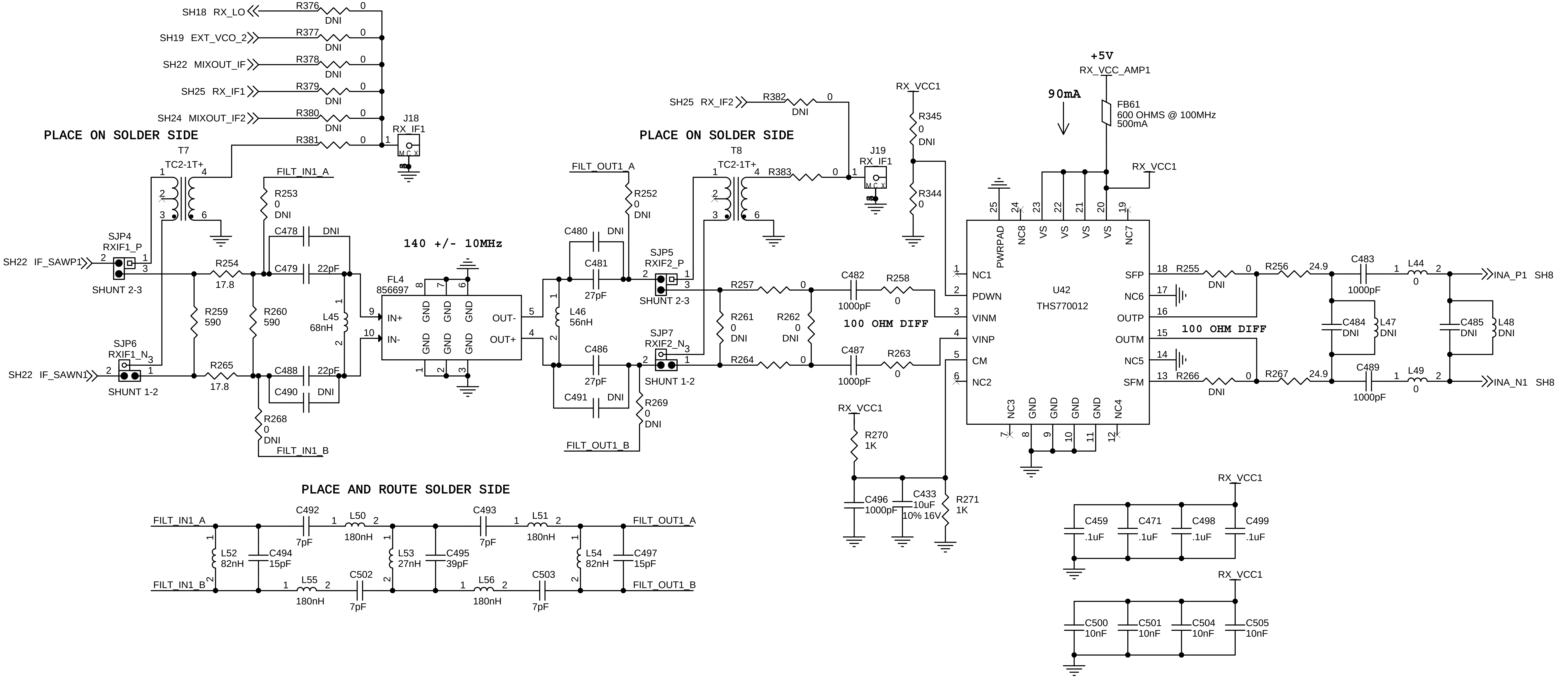
RX AMPLIFIER AND FILTER
PATH 1 (RXIN1)



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RX MIXER AND AMPLIFIER
PATH 2 (RXIN2)

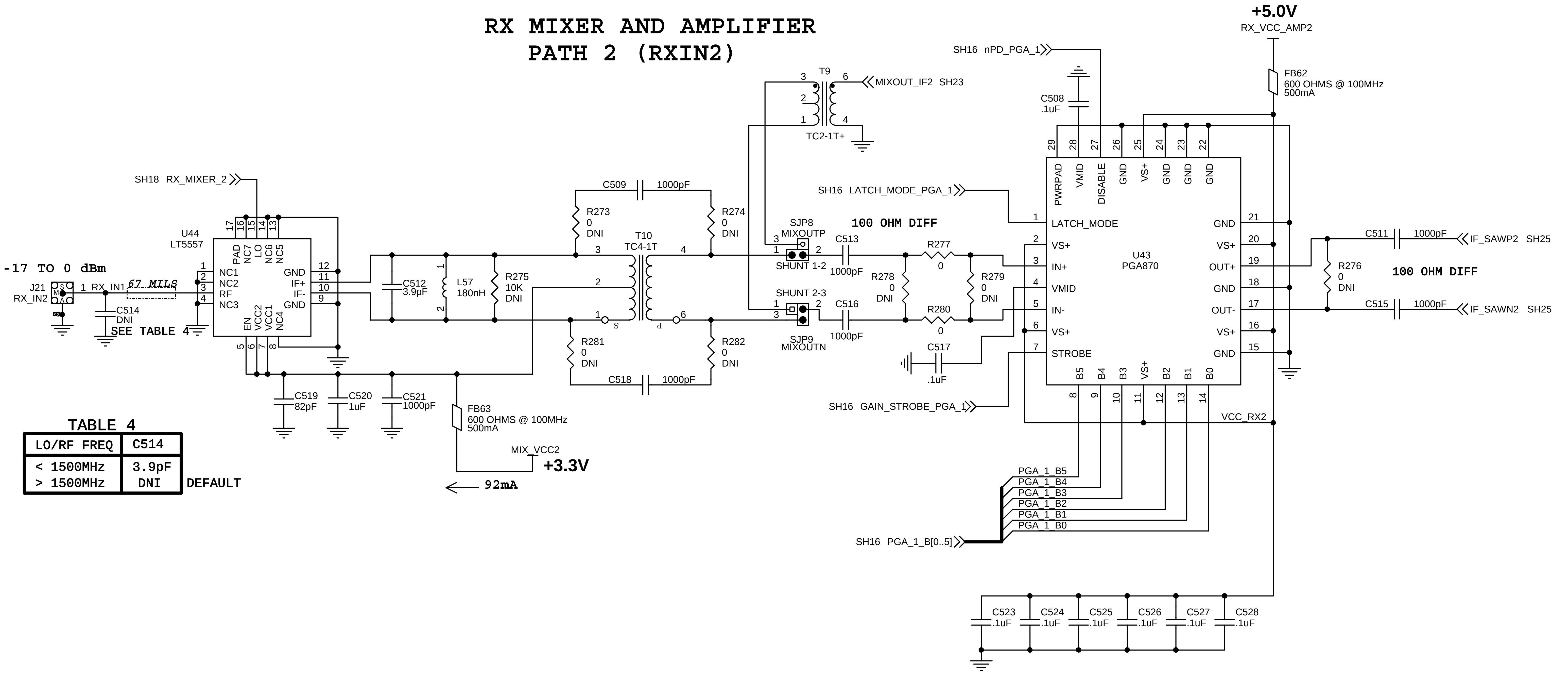

TABLE 4

LO/RF FREQ	C514
< 1500MHz	3.9pF
> 1500MHz	DNI

DEFAULT

TEXAS INSTRUMENTS

Title TSW3725

Size B
Document Number LT5557 & PGA870 - 2
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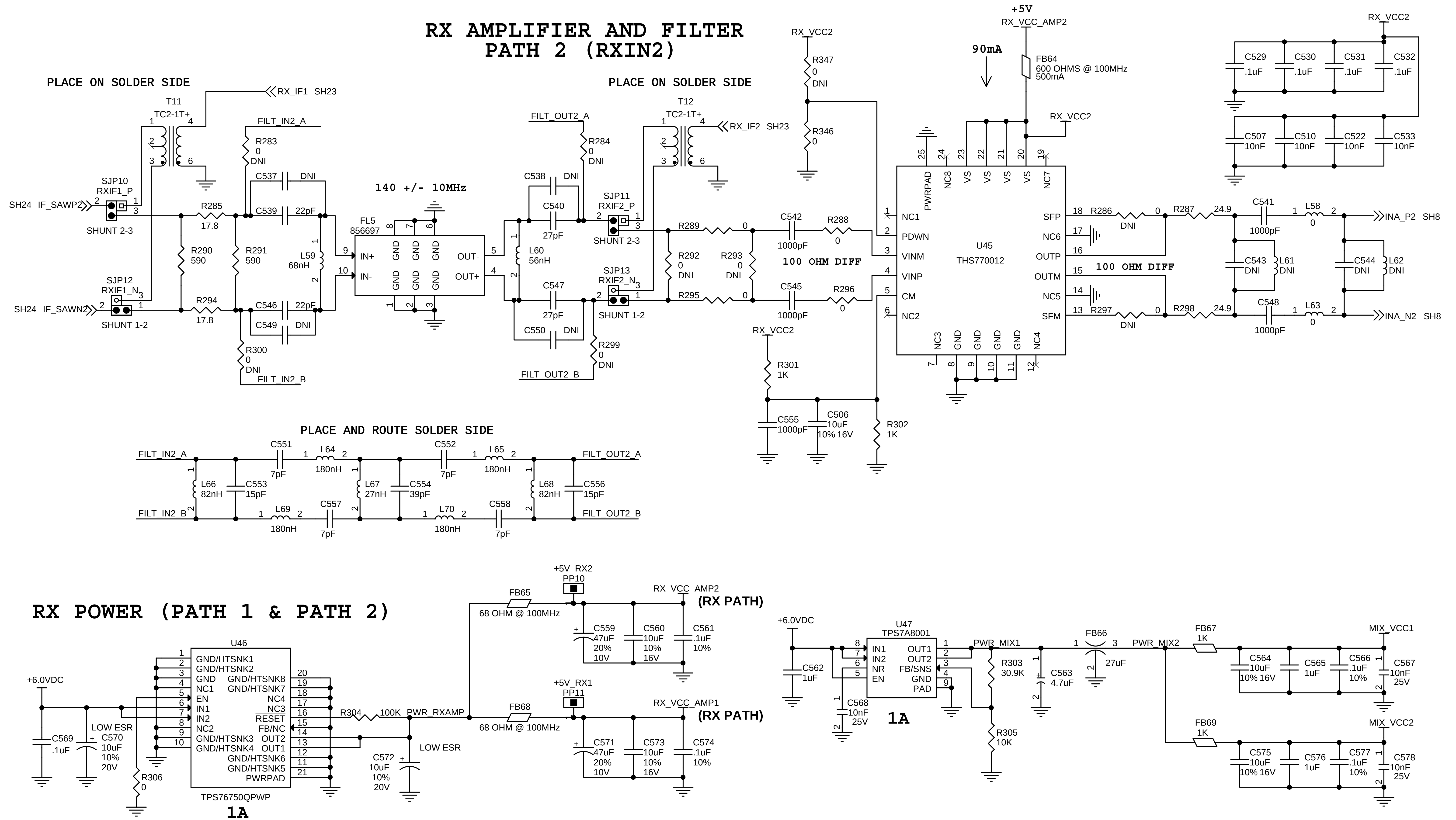
RX AMPLIFIER AND FILTER PATH 2 (RXIN2)

RX POWER (PATH 1 & PATH 2)



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Title	TSW3725		
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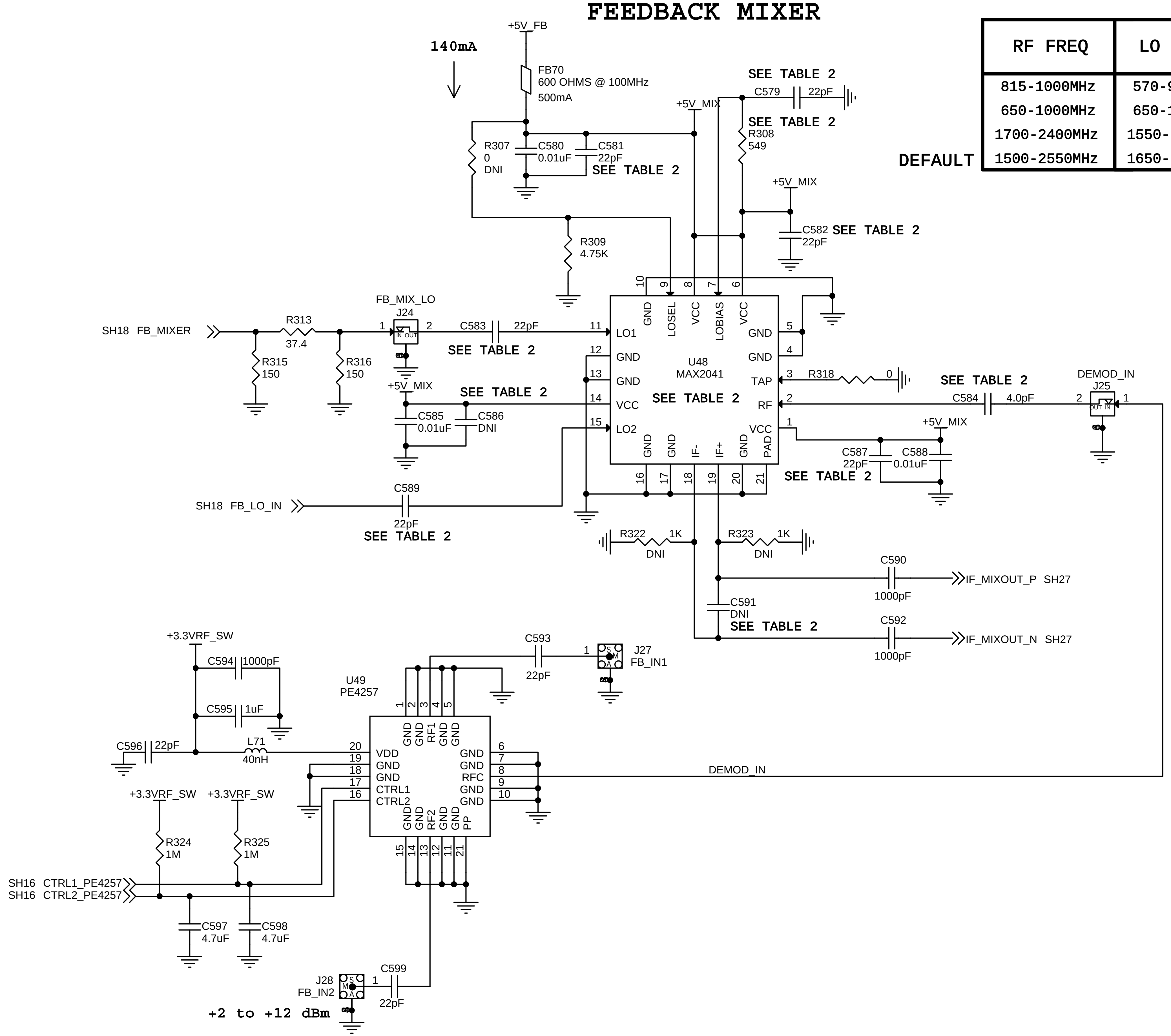

TABLE 2

	RF FREQ	LO FREQ	U48	C579,C581, C583,C587, C589	C582	C586	C584	C591	R308
	815-1000MHz	570-900MHz	MAX2029	82pF	0.01uF	82pF	82pF	3.3pF	523
	650-1000MHz	650-1250MHz	MAX2031	82pF	0.01uF	82pF	82pF	2pF	523
	1700-2400MHz	1550-2250MHz	MAX2039	22pF	22pF	DNI	4pF	DNI	549
DEFAULT	1500-2550MHz	1650-2700MHz	MAX2041	22pF	22pF	DNI	4pF	DNI	549

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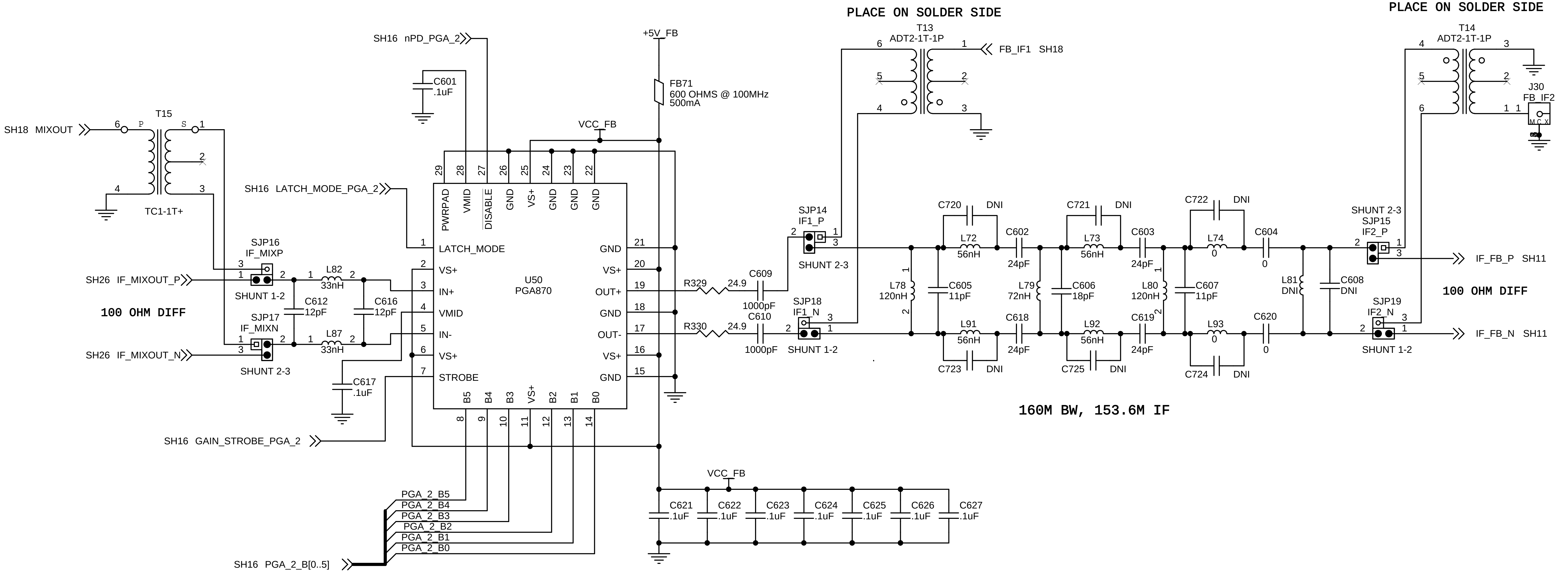
FEEDBACK AMPLIFIER AND FILTER



TEXAS INSTRUMENTS

Title
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B	DEMODULATOR	B

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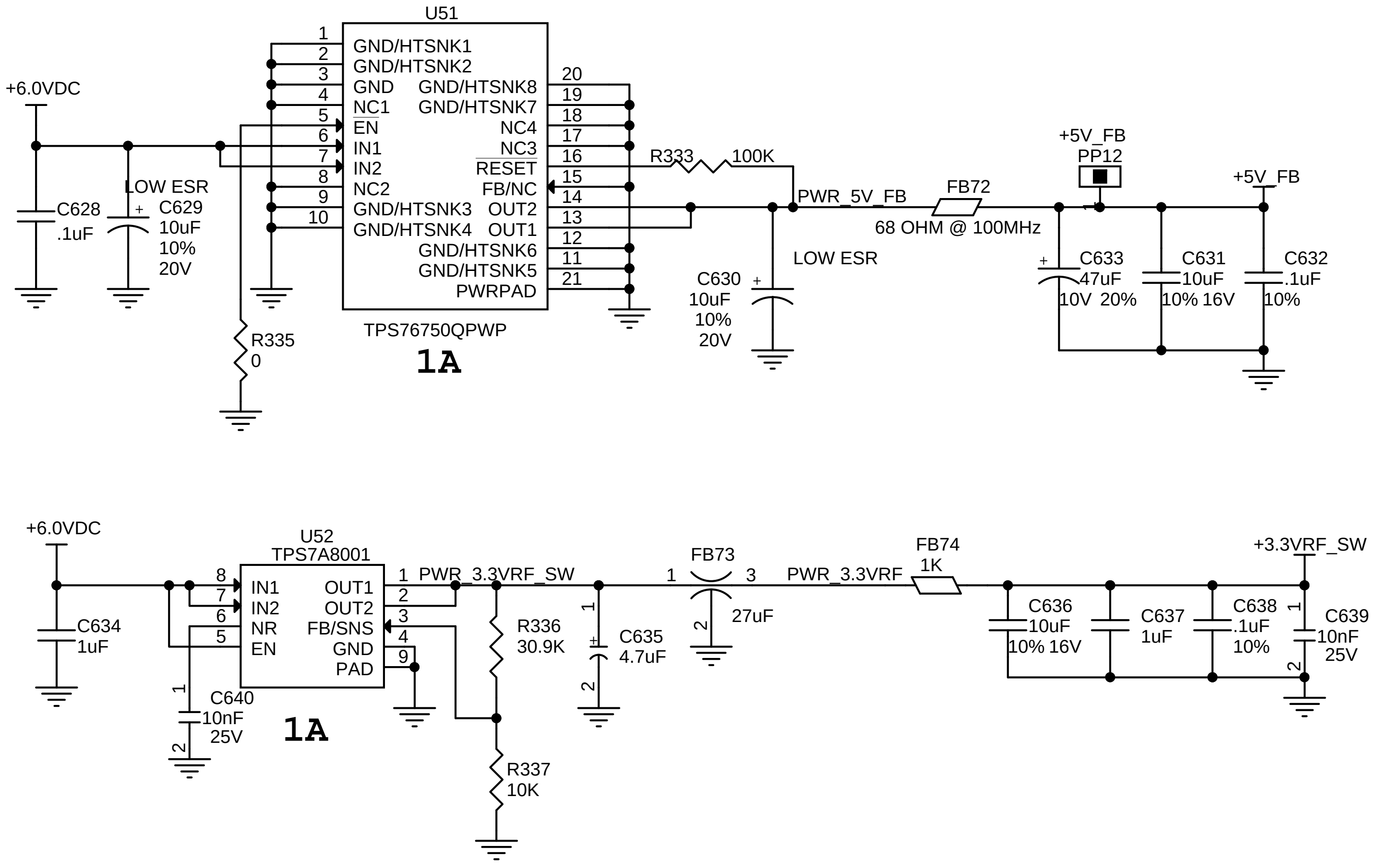

TEXAS INSTRUMENTS

Title	TSW3725	
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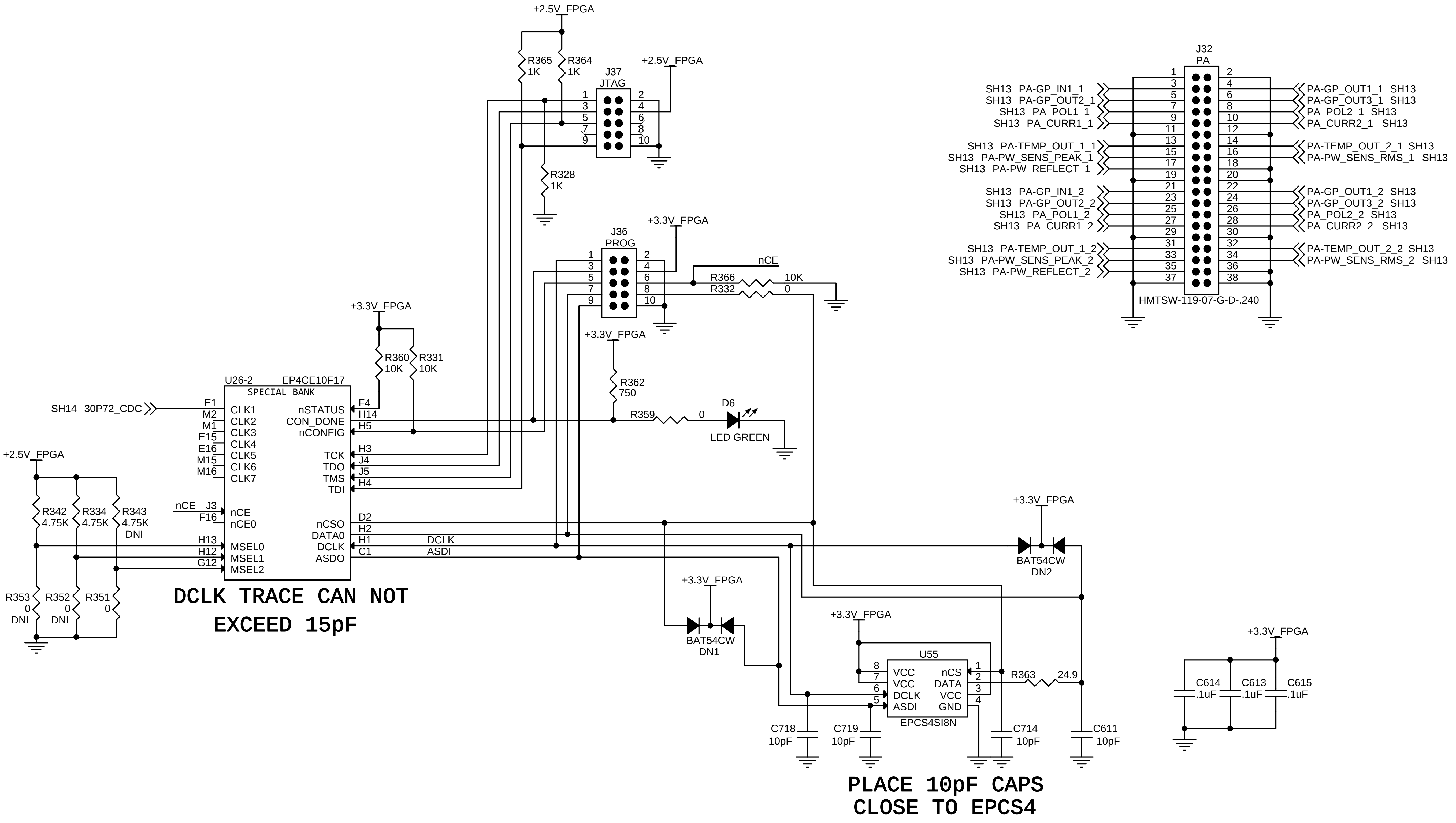

DCLK TRACE CAN NOT
EXCEED 15pF

PLACE 10pF CAPS
CLOSE TO EPCS4

TEXAS INSTRUMENTS

Title	TSW3725	
Size B	Document Number FPGA SPECIAL BANK & PA CONN	Rev B
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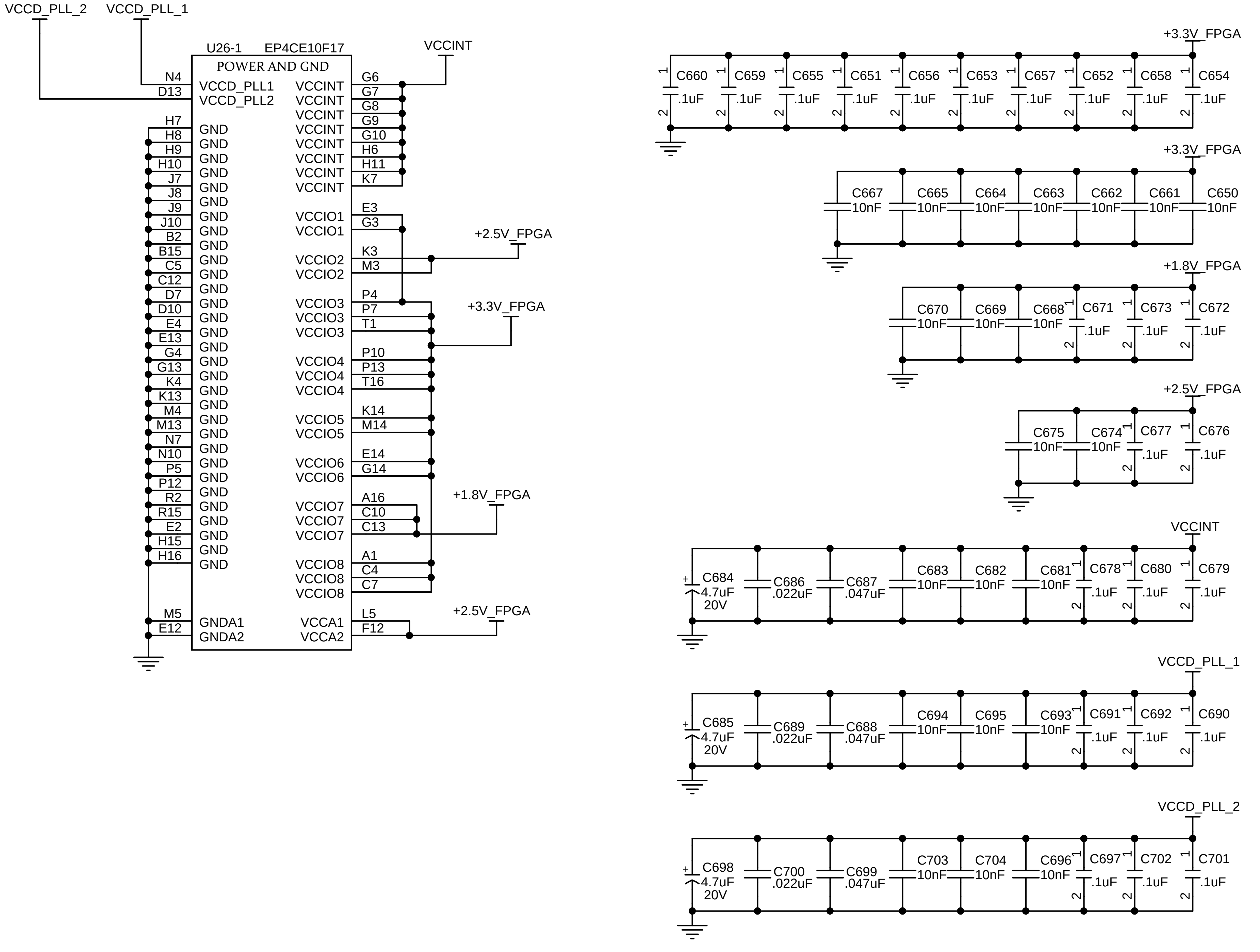

TEXAS INSTRUMENTS

Title
TSW3725

Size	Document Number	Rev
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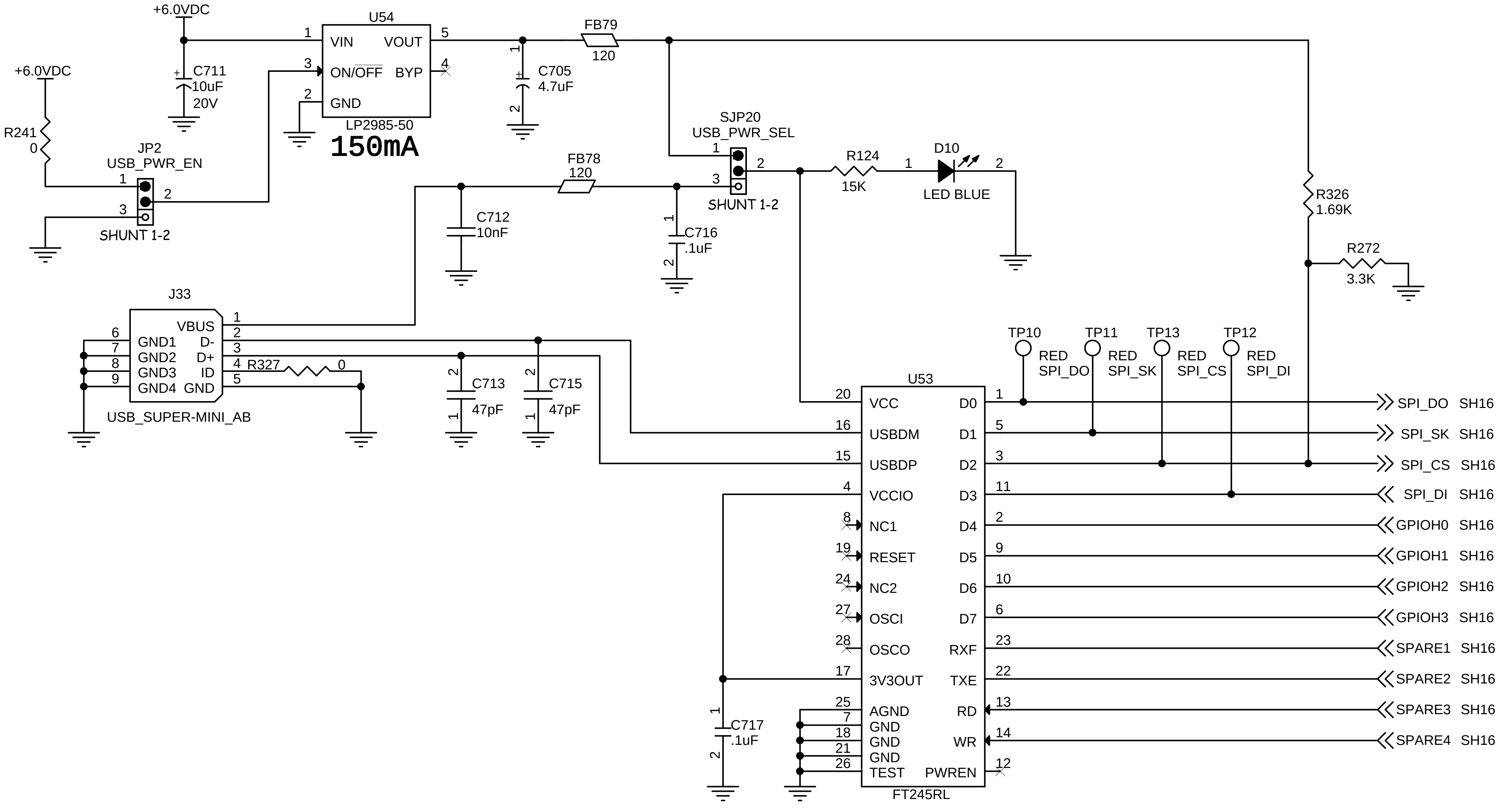
SERIAL INTERFACE



TEXAS INSTRUMENTS

Title	TSW3725	
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